



STV6889

HIGH-END I²C CONTROLLED DEFLECTION PROCESSOR FOR MULTISYNC MONITOR

PRODUCT PREVIEW

FEATURES

General

- Advanced I²C-bus controlled deflection processor dedicated for high-end CRT monitors
- Single supply voltage 12V
- Very low jitter
- DC/DC converter controller
- Advanced EW drive
- Advanced asymmetry corrections
- Automatic multistandard synchronization
- Vertical dynamic correction waveform output
- X-ray protection and Soft-start & stop on horizontal and DC/DC drive outputs
- I²C-bus status register

Horizontal section

- 150 kHz maximum frequency
- Corrections of geometric asymmetry: Pin cushion asymmetry, Parallelogram, separate Top/Bottom corner asymmetry
- Tracking of asymmetry corrections with vertical size and position
- Fully integrated horizontal moiré cancellation

Vertical section

- 200 Hz maximum frequency
- Vertical ramp for DC-coupled output stage with adjustments of: C-correction, S-correction for super-flat CRT, Vertical size, Vertical position
- Vertical size and position prescales for factory adjustment
- Vertical moiré cancellation through vertical ramp waveform
- Compensation of vertical breathing with EHT variation; I²C-bus gain adjustment

EW section

- Symmetrical geometry corrections: Pin cushion, Keystone, Top/Bottom corners separately, S- and W-corrections
- Horizontal size adjustment
- Tracking of EW waveform with Vertical size and position, horizontal size and frequency

- Compensation of horizontal breathing with EHT variation, I²C-bus gain adjustment

Dynamic correction section

- Generates vertical waveform for dynamic corrections like focus, brightness uniformity, ...
- 1 output with vertical dynamic correction waveform, both polarities, tracking with vertical size and position

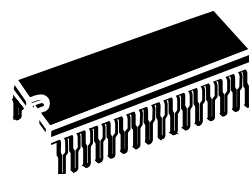
DC/DC controller section

- Step-up and step-down conversion modes
- External sawtooth configuration
- I²C-bus-controlled output voltage
- Synchronized on hor. frequency with phase selection
- Selectable polarity of drive signal
- Protection at H unlock condition

DESCRIPTION

The STV6889 is a monolithic integrated circuit assembled in a 32-pin shrink dual-in-line plastic package. This IC controls all the functions related to horizontal and vertical deflection in multimode or multi-frequency computer display monitors.

Combined with other ST components dedicated for CRT monitors (microcontroller, video preamplifier, video amplifier, OSD controller), the STV6889 allows fully I²C bus-controlled computer display monitors to be built with a reduced number of external components.



SDIP 32 (Shrink DIP package)

ORDER CODE: STV6889

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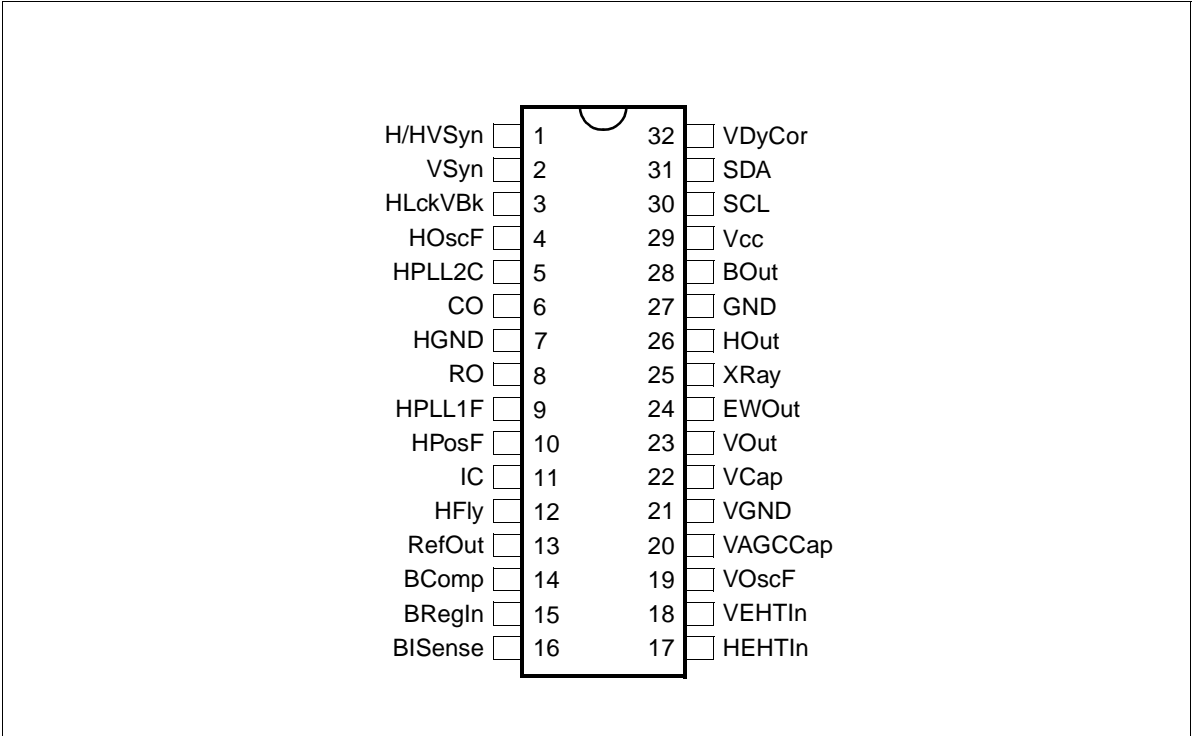
This is preliminary information on a new product now in development. Details are subject to change without notice.

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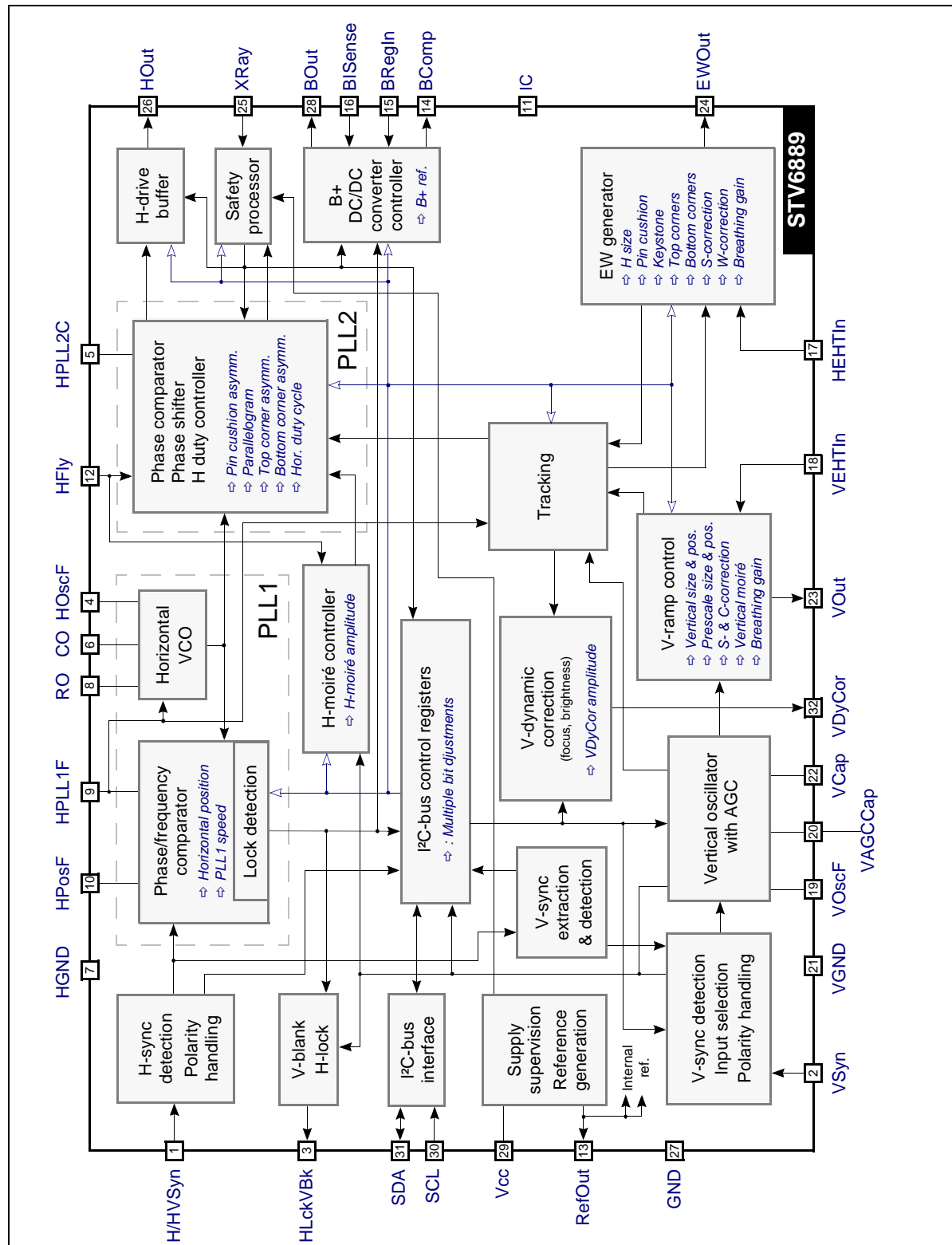
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1 PIN CONFIGURATION



2 BLOCK DIAGRAM



3 PIN FUNCTION REFERENCE

Pin	Name	Function
1	H/HVSyn	TTL compatible H orizontal / H orizontal and V ertical S ync. input
2	VSyn	TTL compatible V ertical S ync. input
3	HLckVBk	H orizontal PLL1 L ock detection and V ertical early B lanking composite output
4	HOscF	High H orizontal O scillator sawtooth threshold level F ilter input
5	HPLL2C	H orizontal P LL2 loop C apacitive filter input
6	CO	Horizontal O scillator C apacitor input
7	HGND	H orizontal section G rou N D
8	RO	Horizontal O scillator R esistor input
9	HPLL1F	H orizontal P LL1 loop F ilter input
10	HPosF	H orizontal P osition F ilter and soft-start time constant capacitor input
11	IC	Internally C onected (to be left open)
12	HFly	H orizontal F lyback input
13	RefOut	R eference voltage O utput
14	BComp	B + DC/DC error amplifier (C ompensation) output
15	BRegIn	R egulation feedback I nput of the B + DC/DC converter controller
16	BISense	B + DC/DC converter current (I) S ense input
17	HEHTIn	I nput for compensation of H orizontal amplitude versus E HT variation
18	VEHTIn	I nput for compensation of V ertical amplitude versus E HT variation
19	VOscF	V ertical O scillator sawtooth low threshold F ilter (capacitor to be connected to VGND)
20	VAGCCap	Input for storage C apacitor for A utomatic G ain C ontrol loop in V ertical oscillator
21	VGND	V ertical section G rou N D
22	VCap	V ertical sawtooth generator C apacitor
23	VOut	V ertical deflection drive O utput for a DC-coupled output stage
24	EWOut	E /W O utput
25	XRy	X - R ay protection input
26	HOut	H orizontal drive O utput
27	GND	Main G rou N D
28	BOut	B + DC/DC converter controller O utput
29	Vcc	Supply voltage
30	SCL	I ² C-bus S erial C lock Input
31	SDA	I ² C-bus S erial D Ata input/output
32	VDyCor	V ertical D ynamic C orrection output

4 QUICK REFERENCE DATA

Characteristic	Value	Unit
General		
Package	SDIP 32	
Supply voltage	12	V
Supply current	65	mA
Application category	High-end	
Means of control • Maximum clock frequency	I ² C-bus • 400	kHz
EW drive	Yes	
DC/DC converter controller	Yes	
Horizontal section		
Frequency range	15 to 150	kHz
Autosync frequency ratio (can be enlarged in application)	4.28	
Positive • Negative polarity of horizontal sync signal • Automatic adaptation	Yes • Yes • Yes	
Duty cycle range of the drive signal	30 to 65	%
Position adjustment range with respect to H period	±10	%
Soft start • Soft stop feature	Yes • Yes	
Hardware • Software PLL lock indication	Yes • Yes	
Parallelogram	Yes	
Pin cushion asymmetry correction (also called Side pin balance)	Yes	
Top • Bottom • Common corner asymmetry correction	Yes • Yes • No	
Tracking of asymmetry corrections with vertical size & position	Yes	
Horizontal moiré cancellation (int.) for Combined • Separated architecture	Yes • Yes	
Vertical section		
Frequency range	35 to 200	Hz
Autosync frequency range (150nF at VCap and 470nF at VAGCCap)	50 to 180	Hz
Positive • Negative polarity of vertical sync signal • Automatic adaptation	Yes • Yes • Yes	
S-correction • C-correction • Super-flat tube characteristic	Yes • Yes • Yes	
Vertical size • Vertical position • Prescale adjustments	Yes • Yes • Yes	
Vertical moiré cancellation (internal)	Yes	
EHT breathing compensation • With I ² C-bus gain control	Yes • Yes	
EW section		
Pin cushion correction	Yes	
Keystone correction	Yes	
Top • Bottom • Common corner correction	Yes • Yes • No	
S-correction • W-correction	Yes • Yes	
Horizontal size adjustment	Yes	
Tracking of EW waveform with Frequency • Vertical size & position	Yes • Yes	
EHT breathing compensation • With I ² C-bus gain control	Yes • Yes	
Dynamic correction section (dyn. focus, dyn. brightness,...)		
Vertical dynamic correction output VDyCor • Positive or negative polarity	Yes • Yes	
Horizontal dynamic correction output HDyCor	No	
Composite HV dynamic correction output HVDyCor • Positive or negative polarity	No • No	
Shape control on H waveform component of HVDyCor output	No	
Tracking of horizontal waveform component with Horizontal size • EHT	No • No	
Tracking of vertical waveforms (component) with V. size & position	Yes	
DC • DC controller section		
Step-up • Step-down conversion mode	Yes • Yes	
Internal • External sawtooth configuration	No • Yes	
Bus-controlled output voltage • Inhibition at H unlock	Yes • Yes	
Mute • Soft start • Soft stop feature	Yes • Yes • Yes	
Positive (N-MOS) • Negative(P-MOS) polarity of BOut signal	Yes • Yes	
Phase selection • Max current selection • Frequency selection	Yes • Yes • Yes	

5 ABSOLUTE MAXIMUM RATINGS

All voltages are given with respect to ground.

Currents flowing from the device (sourced) are signed negative. Currents flowing to the device are signed positive.

Symbol	Parameter	Value		Unit
		Min	Max	
V_{CC}	Supply voltage (pin V_{CC})	-0.4	13.5	V
$V_{(pin)}$	Pins HEHTIn, VEHTIn, XRay, HOut, BOut	-0.4	V_{CC}	V
	Pins H/HVSyn, VSyn, SCL, SDA	-0.4	5.5	V
	Pins HLckVBk, CO, RO, HPLL1F, HPosF, BRegIn, BISense, VAGCCap, VCap, VDyCor, HOscF, VOscF	-0.4	V_{RefO}	V
	Pin HPLL2C	-0.4	$V_{RefO}/2$	V
	Pin HFly	-0.4	V_{RefO}	V
$I_{latch(pin)}$	Latch-up current			
	All pins except XRay Pin XRay	-200 -100	200 200	mA mA
V_{ESD}	ESD susceptibility (human body model: discharge of 100pF through 1.5k Ω)	-2000	2000	V
T_{stg}	Storage temperature	-40	150	°C
T_j	Junction temperature		150	°C

6 ELECTRICAL PARAMETERS AND OPERATING CONDITIONS

Medium (middle) value of an I²C-bus control or adjustment register composed of bits D0, D1,...,Dn is the one having Dn at "1" and all other bits at "0". Minimum value is the one with all bits at 0, maximum value is the one with all at "1".

Currents flowing from the device (sourced) are signed negative. Currents flowing to the device are signed positive.

T_H is period of horizontal deflection.

6.1 Thermal data

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
T _{amb}	Operating ambient temperature	0		70	°C
R _{th(j-a)}	Junction-ambience thermal resistance		65		°C/W

6.2 Supply and Reference voltages

T_{amb} = 25°C

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V _{CC}	Supply voltage at V _{CC} pin		10.8	12	13.2	V
I _{CC}	Supply current to V _{CC} pin	V _{CC} = 12V		65		mA
V _{RefO}	Reference output voltage at RefOut pin	V _{CC} = 12V, I _{RefO} = -2mA	7.65	7.9	8.2	V
I _{RefO}	Current capability of RefOut output		-5		0	mA

6.3 Synchronization inputs

V_{CC} = 12V, T_{amb} = 25°C

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V _{LoH/HVSyn}	LOW level voltage on H/HVSyn		0		0.8	V
V _{HiH/HVSyn}	HIGH level voltage on H/HVSyn		2.2		5	V
V _{LoVSyn}	LOW level voltage on VSyn		0		0.8	V
V _{HiVSyn}	HIGH level voltage on VSyn		2.2		5	V
R _{PdSyn}	Internal pull-down on H/HVSyn, VSyn		100	175	250	kΩ
t _{PulseHSyn}	H sync. pulse duration on H/HVSyn pin		0.5			μs
t _{PulseHSyn} /T _H	Proportion of H sync pulse to H period	Pin H/HVSyn			0.2	
t _{PulseVSyn}	V sync. pulse duration	Pins H/HVSyn, VSyn	0.5		750	μs
t _{PulseVSyn} /T _V	Proportion of V sync pulse to V period	Pins H/HVSyn, VSyn			0.15	
t _{extrV} /T _H	Proportion of H sync pulse length to H period for extraction as V sync pulse	Pin H/HVSyn, cap. on pin CO = 820pF	0.21	0.35		
t _{HPolDet}	Polarity detection time (after change)	Pin H/HVSyn	0.75			ms

6.4 Horizontal section

Table 1. Horizontal section (V_{CC} = 12V, T_{amb} = 25°C)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
PLL1						
I _{RO}	Current load on RO pin				1.5	mA
C _{CO}	Capacitance on CO pin		390			pF
f _{HO}	Frequency of hor. oscillator				150	kHz
f _{HO(0)}	Free-running frequency of hor. oscill. ⁽¹⁾	R _{RO} =5.23kΩ, C _{CO} =820pF	27	28.5	29.9	kHz
f _{HOCapt}	Hor. PLL1 capture frequency ⁽⁴⁾	f _{HO(0)} = 28.5kHz	29		122	kHz
$\frac{\Delta f_{HO(0)}}{f_{HO(0)} \cdot \Delta T}$	Temperature drift of free-running freq. ⁽³⁾			-150		ppm/°C
Δf _{HO} /ΔV _{HO}	Average horizontal oscillator sensitivity	f _{HO(0)} = 28.5kHz		20.2		kHz/V
V _{HO}	H. oscill. control voltage on pin HPLL1F	V _{RefO} =8V	1.4		6.0	V
V _{HOThrfr}	Threshold on H. oscill. control voltage on HPLL1F pin for tracking of EW with freq.	V _{RefO} =8V		5.0		V
V _{HPosF}	Control voltage on HPosF pin	HPOS (Sad01h): 11111111b 10000000b 00000000b		2.8 3.4 4.0		V V V
V _{HOThrLo}	Bottom of hor. oscillator sawtooth ⁽⁶⁾			1.6		V
V _{HOThrHi}	Top of hor. oscillator sawtooth ⁽⁶⁾			6.4		V
PLL2						
R _{In(HFly)}	Input impedance on HFly input	V _(HFly) > V _{ThrHFly} ⁽²⁾	300	500	700	Ω
I _{InHFly}	Current into HFly input	At top of H flyback pulse			5	mA
V _{ThrHFly}	Voltage threshold on HFly input		0.5	0.6		V
V _{S(0)}	H flyback lock middle point ⁽⁶⁾	No PLL2 phase modulation		4.0		V
V _{BotHPLL2C}	Low clamping voltage on HPLL2C pin ⁽⁵⁾			1.6		V
V _{TopHPLL2C}	High clamping voltage on HPLL2C pin ⁽⁵⁾			4.0		V
t _{ph(min)} /T _H	Min. advance of H-drive OFF before middle of H flyback ⁽⁷⁾	Null asym. correction		0		%
t _{ph(max)} /T _H	Max. advance of H-drive OFF before middle of H flyback ⁽⁸⁾	Null asym. correction		44		%
H-drive output on pin HOut						
I _{HOut}	Current into HOut output	Output driven LOW			30	mA
t _{Hoff} /T _H	Duty cycle of H-drive signal	f _H = 31kHz; HDUTY (Sad00h): x1111111b x0000000b Soft-start/Soft-stop value		27 65 85		% % %

Table 1. Horizontal section (V_{CC} = 12V, T_{amb} = 25°C)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
Picture geometry corrections through PLL1 & PLL2						
t_{Hph}/T_H	Hor. VCO phase vs. sync signal (via PLL1), see Figure 7	<i>HPOS</i> (Sad01h): 11111111b 10000000b 00000000b		+11 0 -11		% % %
t_{PCAC}/T_H	Contribution of pin cushion asymmetry correction to phase of H-drive vs. static phase (via PLL2), measured in corners	<i>PCAC</i> (Sad11h) full span ⁽⁹⁾ <i>VPOS</i> at medium <i>VSIZE</i> at minimum <i>VSIZE</i> at medium <i>VSIZE</i> at maximum		±0.9 ±1.6 ±2.6		% % %
t_{ParalC}/T_H	Contribution of parallelogram correction to phase of H-drive vs. static phase (via PLL2), measured in corners	<i>PARAL</i> (Sad12h) full span ⁽⁹⁾ <i>VPOS</i> at medium <i>VSIZE</i> at minimum <i>VSIZE</i> at medium <i>VSIZE</i> at maximum		±1.4 ±1.9 ±2.4		% % %
t_{TCAC}/T_H	Contribution of top corner asymmetry correction to phase of H-drive vs. static phase (via PLL2), measured in corners	<i>TCAC</i> (Sad13h) full span ⁽⁹⁾ <i>VPOS</i> at medium <i>VSIZE</i> at minimum <i>VSIZE</i> at medium <i>VSIZE</i> at maximum		±0.4 ±1.4 ±3.5		% % %
t_{BCAC}/T_H	Contribution of bottom corner asymmetry correction to phase of H-drive vs. static phase (via PLL2), measured in corners	<i>BCAC</i> (Sad14h) full span ⁽⁹⁾ <i>VPOS</i> at medium <i>VSIZE</i> at minimum <i>VSIZE</i> at medium <i>VSIZE</i> at maximum		±0.4 ±1.4 ±3.5		% % %

Notes about horizontal section

- Note 1:** Frequency at no sync signal condition. For correct operation, the frequency of the sync signal applied must always be higher than the free-running frequency. The application must consider the spread of values of real electrical components in R_{RO} and C_{CO} positions so as to always meet this condition. The formula to calculate the free-running frequency is $f_{HO(0)} = 0.122 / (R_{RO} C_{CO})$
- Note 2:** Base of NPN transistor with emitter to ground is internally connected on pin [HFLy](#) through a series resistance of about 500Ω and a resistance to ground of about 20kΩ.
- Note 3:** Evaluated and figured out during the device qualification phase. Informative. Not tested on every single unit.
- Note 4:** This capture range can be enlarged by external circuitry.
- Note 5:** The voltage on [HPLL2C](#) pin corresponds to immediate phase of leading edge of H-drive signal on [HOut](#) pin with respect to internal horizontal oscillator sawtooth. It must be between the two clamping levels given. Voltage equal to one of the clamping values indicates a marginal operation of PLL2 or non-locked state.
- Note 6:** Internal threshold. See [Figure 6](#).
- Note 7:** The $t_{ph(min)}$ parameter is fixed by the application. For correct operation of asymmetry corrections through dynamic phase modulation, this minimum must be increased by maximum of the total dynamic phase required in the direction leading to bending of corners to the left. Marginal situation is indicated by reach of $V_{TopHPLL2C}$ high clamping level by waveform on pin [HPLL2C](#). Also refer to [Note 5](#) and [Figure 6](#).

Notes about horizontal section (continued)

Note 8: The $t_{ph(max)}$ parameter is fixed by the application. For correct operation of asymmetry corrections through dynamic phase modulation, this maximum must be reduced by maximum of the total dynamic phase required in the direction leading to bending of corners to the right. Marginal situation is indicated by reach of $V_{BotHPLL2C}$ low clamping level by waveform on pin **HPLL2C**. Also refer to **Note 5** and **Figure 6**.

Note 9: All other dynamic phase corrections of picture asymmetry set to their neutral (medium) positions.

6.5 Vertical section

Table 2. Vertical section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
AGC-controlled vertical oscillator sawtooth; $V_{RefO} = 8V$						
$R_{L(VAGCCap)}$	Ext. load resistance on $VAGCCap$ pin ⁽¹⁰⁾	$\Delta V_{amp}/V_{amp}(R=\infty) \leq 1\%$	65			MΩ
V_{VOB}	Sawtooth bottom voltage on $VCap$ pin ⁽¹¹⁾	No load on $VOscF$ pin ⁽¹¹⁾		2		V
V_{VOTref}	Sawtooth top voltage internal reference			5		V
V_{VOT}	Sawtooth top voltage on $VCap$ pin	AGC loop stabilized		5		V
t_{VODis}	Sawtooth Discharge time	$C_{VCap}=150nF$		80		μs
$f_{VO(0)}$	Free-running frequency	$C_{VCap}=150nF$		100		Hz
f_{VOCapt}	AGC loop capture frequency	$C_{VCap}=150nF$	50		185	Hz
$\frac{\Delta V_{VOdev}}{V_{VOamp}}$	Sawtooth non-linearity ⁽¹²⁾⁽¹⁷⁾	AGC loop stabilized ⁽¹²⁾		0.5		%
$\frac{\Delta V_{VOamp}}{V_{VOamp} \cdot \Delta f_{VO}}$	Frequency drift of sawtooth amplitude ⁽¹⁸⁾⁽¹⁹⁾	AGC loop stabilized $f_{VOCapt(min)} \leq f_{VO} \leq f_{VOCapt(max)}$		200		ppm/Hz
Vertical output drive signal (on pin $VOut$); $V_{RefO} = 8V$						
V_{midref}	Internal reference for vertical sawtooth middle point			3.5		V
$V_{mid(VOut)}$	Middle point on $VOut$ sawtooth	$VPOS$ (Sad08h): ⁽²²⁾ x0000000b x1000000b x1111111b $VPOF$ (Sad1Eh): ⁽²¹⁾ x0000000b x1000000b x1111111b	3.65	3.1 3.45 3.8 3.3 3.45 3.6	3.3	V V V V V V
V_{amp}	Amplitude of $VOut$ sawtooth (peak-to-peak voltage)	$VSIZE$ (Sad07h): ⁽²³⁾ x0000000b x1000000b x1111111b $VSAG$ (Sad1Dh): ⁽²⁰⁾ x0000000b x1000000b x1111111b	3.5	2.25 3.0 3.75 2 2.5 3.0	2.5	V V V V V V
$V_{offVOut}$	Level on $VOut$ pin at V-drive "off"	I ² C-bus bit $VOutEn$ at 0		4.0		V

Table 2. Vertical section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I_{VOut}	Current delivered by V_{Out} output		-5		0.25	mA
V_{SCor}/V_{amp}	S-correction range	(13)(20)(21) AGC loop stabilized $t_{VR}=1/4 T_{VR}$ (15) $t_{VR}=3/4 T_{VR}$		-4.5 +4.5		% %
V_{CCor}/V_{amp}	C-correction range	(14)(20)(21) AGC loop stabilized $t_{VR}=1/2 T_{VR}$ (15) $CCOR(Sad0Ah)$: x0000000b x1000000b x1111111b		-2.5 0 +2.5		% % %
V_{VEHT}	Control input voltage range on- $VEHTIn$ pin		1	4	6	V
$V_{VEHTnull}$	Neutral point on breathing characteristics ⁽¹⁶⁾			4.0		V
$\frac{\Delta V_{amp}}{V_{amp} \cdot \Delta V_{VEHT}}$	Breathing compensation	$V_{RefO} < V_{VEHT} < V_{CC}$ $V_{VEHT(min)} \leq V_{VEHT} \leq V_{VE-}$ $HT(max)$: $VEHTG$ (Sad1Ch): x0000000b x1000000b x1111111b		0 5 0 -5		%/V %/V %/V %/V

Notes about vertical section

Note 10: Value of acceptable cumulated parasitic load resistance due to humidity, AGC storage capacitor leakage, etc., for less than 1% of V_{amp} change.

Note 11: The threshold for V_{VOB} is generated internally and routed to $VOscF$ pin. Any DC current on this pin will influence the value of V_{VOB} .

Note 12: Maximum of deviation from an ideally linear sawtooth ramp at null S-correction ($SCOR$ at 0000000b) and null C-correction ($CCOR$ at 1000000b). The same rate applies to V-drive signal on V_{Out} pin, no effect on EW_{Out} .

Note 13: Maximum S-correction ($SCOR$ at x1111111b), null C-correction ($CCOR$ at 1000000b).

Note 14: Null S-correction ($SCOR$ at 0000000b).

Note 15: " t_{VR} " is time from the beginning of vertical ramp of V-drive signal on V_{Out} pin. " T_{VR} " is the duration of this ramp, see Chapter 7 - page 21 and Figure 17.

Note 16: If $V_{VEHT}=V_{VEHTnull}$ or $V_{HEHT}=V_{HEHTnull}$, respectively, the influence of V_{VEHT} on vertical drive amplitude or the influence of V_{HEHT} on EW drive signal, respectively, is null.

Note 17: $V_{VOamp} = V_{VOT} - V_{VOB}$

Note 18: Only the top of the saw tooth drifts. The same rate applies to V-drive signal on V_{Out} pin.

Note 19: Informative, not tested on each unit.

Note 20: V_{SIZE} at medium value 1000000b.

Note 21: V_{POS} at medium value 1000000b.

Note 22: V_{POF} at medium value 1000000b.

Note 23: V_{SAG} at maximum value 1111111b.

6.6 EW drive section

Table 3. EW drive section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V_{EW}	Output voltage on EWOut pin		1.8		6.5	V
I_{EWOut}	Current delivered by EWOut output		-1.5		0.1	mA
V_{HEHT}	Control voltage range on HEH-TIn pin		1		6	V
$V_{HEHTnull}$	Neutral point on breathing characteristics. See Figure 15 . ⁽¹⁶⁾			4.0		V
V_{EW-DC}	DC component of the EW-drive signal on EWOut pin ⁽³⁰⁾	(24)(25)(26)(27)(28)(36)(42)(43) EWTrHFr=0 or $V_{HO} > V_{HOThrfr}$ HSIZE (Sad10h): 00000000b 10000000b 11111111b		2 3.25 4.5		V V V
$V_{EW-base}$	DC reference for the EW-drive signal on EWOut pin			2		V
$\frac{\Delta V_{EW-DC}}{\Delta V_{HEHT}}$	Breathing compensation on DC component of the EW-drive signal ⁽³⁰⁾	(24)(25)(26)(27)(42)(43) $V_{RefO} < V_{HEHT} < V_{CC}$ $V_{HEHT(min)} \leq V_{HEHT} \leq V_{HEHT(max)}$ HEHTG (Sad1Bh): x0000000b x1000000b x1111111b		0 0 -0.25 0 +0.25		V/V V/V V/V V/V V/V
$\frac{\Delta V_{EW-DC}}{V_{EW-DC} \cdot \Delta T}$	Temperature drift of DC component of the EW-drive signal ⁽³⁰⁾	(24)(25)(26)(27)(28)(36)(42)(43)(44)		100		ppm/°C
V_{EW-PCC}	Pin cushion correction component of the EW-drive signal	(24)(25)(26)(28)(29)(31)(32)(36)(42)(43) VSIZE at maximum PCC (Sad0Ch): x0000000b x1000000b x1111111b Tracking with VSIZE: PCC at x1000000b VSIZE (Sad07h): x0000000b x1000000b		0 0.75 1.5 0.25 0.5		V V V V V
$\frac{V_{EW-PCC}[t_{vr}=0]}{V_{EW-PCC}[t_{vr}=T_{VR}]}$	Tracking of PCC component of the EW-drive signal with vertical position adjustment	(24)(25)(26)(29)(33)(35)(36)(42)(43) PCC at x1111111b VPOS (Sad08h): x0000000b x1111111b		0.5 2.0		
V_{EW-Key}	Keystone correction component of the EW-drive signal	(25)(26)(27)(28)(29)(33)(34)(36)(42)(43) KEYST (Sad0Dh): x0000000b x1111111b		0.4 -0.4		V V

Table 3. EW drive section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
$V_{EW-TCor}$	Top corner correction component of the EW-drive signal	(24)(26)(27)(28)(29)(31)(33)(36)(42)(43) <i>TCC</i> (Sad0Eh): x0000000b x1000000b x1111111b		-1.4 0 +1.4		V V V
$V_{EW-BCor}$	Bottom corner correction component of the EW-drive signal	(24)(25)(27)(28)(29)(32)(33)(36)(42)(43) <i>BCC</i> (Sad0Fh): x0000000b x1000000b x1111111b		-1.4 0 +1.4		V V V
V_{EW-S}	Pin Cushion S correction component of EW-drive signal	(24)(25)(26)(27)(28)(29)(33)(36)(41)(43) <i>EWSC</i> (Sad19h): x0000000b x1000000b x1111111b		-0.3 0 0.3		V V V
V_{EW-W}	Pin Cushion W correction component of EW-drive signal	(24)(25)(26)(27)(28)(29)(33)(36)(41)(42) <i>EWWC</i> (Sad1Ah): x0000000b x1000000b x1111111b		-0.1 0 0.1		V V V
$\frac{\Delta V_{EW-AC}}{V_{EW-AC}[f_{max}] \cdot \Delta V_{HO}}$	Tracking of AC component of EW-drive signal with horizontal frequency(37)(38)(39)	I ² C bit EWTrHFr=1 $V_{HO} > V_{HOThrfr}$ $V_{HO(min)} \leq V_{HO} \leq V_{HOThrfr}$		0 20		%/V %/V
$\frac{\Delta V_{EW-DC}}{V_{EW-DC}[span] \cdot \Delta V_{HO}}$	Tracking of DC component of EW-drive signal with horizontal frequency(30)(38)(39)	I ² C bit EWTrHFr=1 $V_{HO} > V_{HOThrfr}$ $V_{HO(min)} \leq V_{HO} \leq V_{HOThrfr}$		0 20		%/V %/V
$\frac{V_{EW-AC}}{V_{EW-AC}[HSIZE_{max}]}$	Tracking of AC component of EW-drive signal with horizontal size(37)	I ² C bit EWTrHSize=1 <i>HSIZE</i> (Sad10h): 0000000b 1000000b 1111111b		138 119 100		% % %
$\frac{\Delta V_{EW-AC}}{V_{EW-AC} \cdot \Delta V_{HEHT}}$	Breathing compensation on AC component of the EW-drive signal(37)	$V_{RefO} < V_{HEHT} < V_{CC}$ $V_{HEHT(min)} \leq V_{HEHT} \leq V_{HEHT(max)}$ <i>HEHTG</i> (Sad1Bh): 0000000b 1000000b 1111111b		0 3.5 0 -3.5		%/V %/V %/V

Notes about EW drive section

Note 24: *KEYST* at medium (neutral) value.

Note 25: *TCC* at medium (neutral) value.

Note 26: *BCC* at medium (neutral) value.

Note 27: *PCC* at minimum value.

Note 28: *VPOS* at medium (neutral) value.

Note 29: *HSIZE* I²C field at maximum value.

Note 30: V_{EW-DC} is defined as voltage at $t_{VR}=1/2 T_{VR}$.

Note 31: Defined as difference of (voltage at $t_{VR}=0$) minus (voltage at $t_{VR}=1/2 T_{VR}$).

Note 32: Defined as difference of (voltage at $t_{VR}=T_{VR}$) minus (voltage at $t_{VR}=1/2 T_{VR}$).

Note 33: *VSIZE* at maximum value.

Note 34: Difference (voltage at $t_{VR}=0$) minus (voltage at $t_{VR}=T_{VR}$).

Note 35: Ratio "A/B" of parabola component voltage at $t_{VR}=0$ versus parabola component voltage at $t_{VR}=T_{VR}$.
See [Figure 2](#).

Note 36: $V_{HEHT} > V_{RefO}$, $V_{VEHT} > V_{RefO}$

Note 37: V_{EW-AC} is defined as overall peak-to-peak value between $t_{VR}=0$ and $t_{VR}=T_{VR}$ of all components other than V_{EW-DC} (contribution of PCC, keystone correction, corner corrections and S- and W-corrections).

Note 38: More precisely tracking with voltage on [HPLL1F](#) pin which itself depends on frequency at a rate given by external components on PLL1 pins

Note 39: $V_{EW-DC}[span] = V_{EW-DC}[V_{HO} > V_{HOThrfr}] - V_{EW-DC}[HSIZE=0000000b]$.
 $V_{EW-AC}[f_{max}] = V_{EW-AC}[V_{HO} > V_{HOThrfr}]$.

Note 40: Defined as difference of (voltage at $t_{VR}=1/4 T_{VR}$) minus (voltage at $t_{VR}=3/4 T_{VR}$).

Note 41: Defined as difference of (voltage at $t_{VR}=1/2 T_{VR}$) minus (voltage at $t_{VR}=1/4 T_{VR}$).

Note 42: *EWSC* at medium (neutral) value.

Note 43: *EWWC* at medium (neutral) value.

Note 44: Informative, not tested on each unit.

6.7 Dynamic correction outputs section

Table 4. Dynamic correction outputs section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
Vertical Dynamic Correction output VDyCor						
I_{VDyCor}	Current delivered by VDyCor output		-1.5		0.1	mA
V_{VD-DC}	DC component of the drive signal on VDyCor output	R _{L(VDyCor)} =10kΩ		4		V
V_{VD-V}	Amplitude of V-parabola on VDyCor output	(28) VSIZE at medium VDC-AMP (Sad15h): x0000000b x1000000b x1111111b VDC-AMP at maximum VSIZE (Sad07h): x0000000b x1111111b		0 0.5 1 0.6 1.6		V V V V V
$\frac{V_{VD-V}[t_{VR}=0]}{V_{VD-V}[t_{VR}=T_{VR}]}$	Tracking of V-parabola on VDyCor output with vertical position (45)	VDC-AMP at maximum VPOS (Sad08h): x0000000b x1111111b		0.5 2.0		

Notes about dynamic output section

Note 45: Ratio "A/B" of vertical parabola component voltage at $t_{VR}=0$ versus vertical parabola component voltage at $t_{VR}=T_{VR}$.

6.8 DC/DC controller section

Table 5. DC/DC controller section ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
R_{B+FB}	Ext. resistance applied between BComp output and BRegIn input		5			$k\Omega$
A_{OLG}	Open loop gain of error amplifier on BRegIn input	Low frequency ⁽¹⁹⁾		100		dB
f_{UGBW}	Unity gain bandwidth of error amplifier on BRegIn input	⁽¹⁹⁾		6		MHz
I_{RI}	Bias current delivered by BRegIn			-0.2		μA
I_{BComp}	Output current capability of BComp output.	BOut enabled BOut disabled ⁽⁴⁶⁾	-0.5	0.5	2.0	mA mA
$A_{BISense}$	Voltage gain on BISense input			3		
$V_{ThrBIsCurr}$	Threshold voltage on BISense input corresponding to current limitation	$ThrBIsense = 0$ $ThrBIsense = 1$	TBD TBD	2.1 1.2		V
$I_{BISense}$	Bias current delivered by BISense			-1		μA
t_{BOn}	Conduction time of the power transistor				$T_H - 300ns$	
I_{BOut}	Output current capability of BOut output		0		10	mA
V_{BOSat}	Saturation voltage of the internal output transistor on BOut	$I_{BOut}=10mA$		0.25		V
V_{BReg}	Regulation reference for BRegIn voltage ⁽⁴⁷⁾	$V_{RefO}=8V$ $BREF$ (Sad03h): x0000000b x1000000b x1111111b		3.8 4.9 6.0		V V V
$t_{BTrigDel}/T_H$	Delay of BOut "Off-to-On" edge after middle of flyback pulse ⁽⁴⁸⁾	$BOutPh = 0$ and $BO-HEdge = 0$		16		%

Note 46: A current sink is provided by the **BComp** output while **BOut** is disabled.

Note 47: Internal reference related to V_{RefO} . The same values to be found on pin **BRegIn**, while regulation loop is stabilized.

Note 48: Only applies to configuration specified in "Test conditions" column, i.e. synchronization of **BOut** "Off-to-On" edge with horizontal fly-back signal. Refer to chapter "DC/DC controller" for more details.

6.9 Miscellaneous

Table 6. Miscellaneous ($V_{CC} = 12V$, $T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
Vertical blanking and horizontal lock indication composite output HLckVBk						
I _{SinkLckBk}	Sink current to HLckVBk pin	(49)		100		μA
V _{OLckBk}	Output voltage on HLckVBk output	V. blank				
		H. lock				
		No	Yes		0.1	V
		Yes	Yes		1.1	V
		No	No		5	V
Yes	No		6	V		
Horizontal moiré canceller						
$\frac{\Delta T_{H(H-moiré)}}{T_H}$	Modulation of T _H by H. moiré function	HMOiréMode = 0 HMOIRE (Sad02h): x0000000b x1111111b		0 0.02		% %
		HMOiréMode = 1 HMOIRE (Sad02h): x0000000b x1111111b		0 0.04		% %
Vertical moiré canceller						
V _{V-moiré}	Amplitude of modulation of V-drive signal on VOut pin by vertical moiré.	VMOIRE (Sad0Bh): x0000000b x1111111b		0 3		mV mV
Protection functions						
V _{ThrXRay}	Input threshold on XRay input(50)		V _{RefO} -10mV	V _{RefO}	V _{RefO} +10mV	
t _{XRayDelay}	Delay time between XRay detection event and protection action		T _H		2T _H	
V _{CCXRayEn}	Minimum V _{CC} value for operation of XRay detection and protection(53)			10.2	10.8	V
V _{CCEn}	V _{CC} value for start of operation at V _{CC} ramp-up(51)			8.0		V
V _{CCDis}	V _{CC} value for stop of operation at V _{CC} ramp-down(51)			6.8		V
Control voltages on HPosF pin and V _{CC} for Soft start/stop operation(19)(52)						
V _{HOn}	Threshold for start/stop of H-drive signal			1		V
V _{BOn}	Threshold for start/stop of B-drive signal			1.7		V
V _{HBNorm}	Threshold for full operation duty cycle of H-drive and B-drive signals			2.4		
V _{CCStop}	Minimum supply voltage when voltage on HPosF pin reaches V _{HOn} threshold(54)			4.8		

Notes about Miscellaneous section

Note 49: Current sunk by the pin if the external voltage is higher than one the circuit tries to force.

Note 50: See V_{RefO} in [Section 6.2](#).

Note 51: In the regions of V_{CC} where the device's operation is disabled, the H-drive, V-drive and B+-drive signals on [HOut](#), [VOut](#) and [BOut](#) pins, resp., are inhibited, the I²C-bus does not accept any data and the [XRayAlarm](#) flag is reset. Also see [Figure 10](#).

Note 52: See [Figure 10](#).

Note 53: When V_{CC} is below $V_{CCXRyEn}$ XRay detection and protection are disabled.

Note 54: Minimum momentary supply voltage to ensure a correct performance of Soft stop function at V_{CC} fall down is defined at the moment when the voltage on [HPosF](#) pin reaches V_{HOn} threshold.

7 TYPICAL OUTPUT WAVEFORMS

Table 7. Typical output waveforms - Note 55


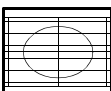

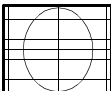

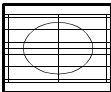

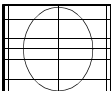
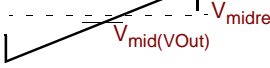
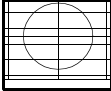
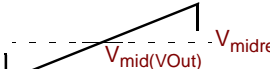
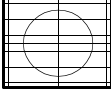
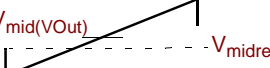
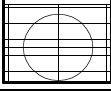
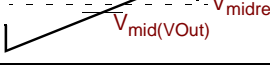
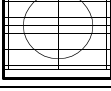
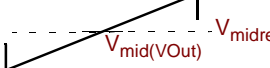
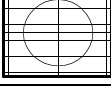
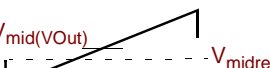
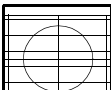
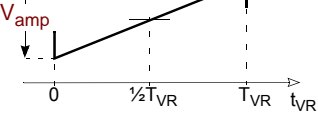
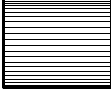
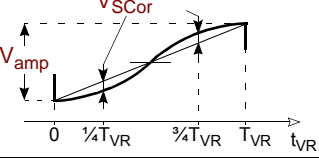
Function	Sad	Pin	Byte	Waveform	Effect on Screen
Vertical Size	07	VOut (23)	x0000000		
			x1111111		
Vertical Size After Gain	1D	VOut (23)	x0000000		
			x1111111		
Vertical Position	08	VOut (23)	x0000000		
			x1000000		
			x1111111		
Vertical Position Offset	1E	VOut (23)	x0000000		
			x1000000		
			x1111111		
S-correction	09	VOut (23)	x0000000: Null		
			x1111111: Max.		

Table 7. Typical output waveforms - Note 55

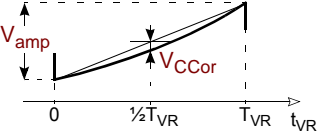
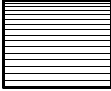
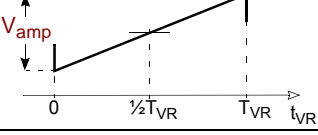
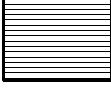
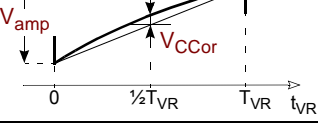
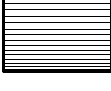
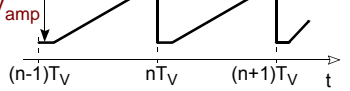

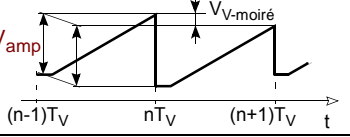
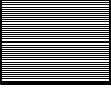
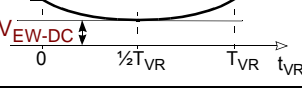

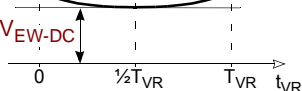
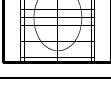
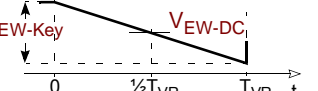

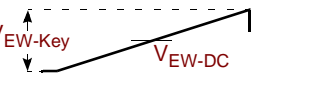

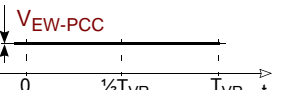
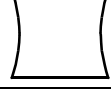
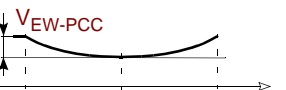

Function	Sad	Pin	Byte	Waveform	Effect on Screen
C-correction	0A	VOut (23)	x0000000		
			x1000000 : Null		
			x1111111		
Vertical moiré amplitude	0B	VOut (23)	x0000000: Null		
			x1111111: Max.		
Horizontal size	10h	EWOOut (24)	00000000		
			11111111		
Keystone correction	0D	EWOOut (24)	x0000000		
			x1111111		
Pin cushion correction	0C	EWOOut (24)	x0000000		
			x1111111		

Table 7. Typical output waveforms - Note 55

Function	Sad	Pin	Byte	Waveform	Effect on Screen
Top corner correction	0E	EWOOut (24)	x11111111		
			x00000000		
Bottom corner correction	0F	EWOOut (24)	x11111111		
			x00000000		
Pin Cushion S-correction	19	EWOOut (24)	x11111111		
			x00000000		
Pin Cushion W-correction	1A	EWOOut (24)	x11111111		
			x00000000		
Parallelogram correction	12h	Internal	x00000000		
			x11111111		
Pin cushion asymmetry correction	11h	Internal	x00000000		
			x11111111		

Table 7. Typical output waveforms - Note 55

Function	Sad	Pin	Byte	Waveform	Effect on Screen
Top corner asymmetry correction	13h	Internal	x0000000		
			x1111111		
Bottom corner asymmetry correction	14h	Internal	x0000000		
			x1111111		
Vertical dynamic correction amplitude	15h	VDyCor (32)	01111111		Application dependent
			x0000000		
			11111111		

Note 55: For any H and V correction component of the waveforms on **EWOut** and **VOut** pins and internal waveform for corrections of H asymmetry, displayed in the table, the weight of the other relevant components is nullified (minimum for parabola, S-correction, medium for keystone, all corner corrections, C-correction, S- and W-pin cushion corrections, parallelogram, pin cushion asymmetry correction, written in corresponding registers).

8 I²C-BUS CONTROL REGISTER MAP

The device slave address is 8C in write mode and 8D in read mode. The control register map is given in Table .

Bold weight denotes default value at Power-On-Reset.

I²C-bus data in the adjustment register is buffered and internally applied with discharge of the vertical oscillator ⁽⁵⁶⁾.

In order to ensure compatibility with future devices, all "Reserved" bits should be set to 0.

Table 8. I²C-bus control registers

Sad	D7	D6	D5	D4	D3	D2	D1	D0
WRITE MODE (SLAVE ADDRESS = 8C)								
00	HDutySyncV 1: Synchro. 0: Asynchro.	<i>HDUTY</i> Horizontal duty cycle						
		0	0	0	0	0	0	0
01		<i>HPOS</i> Horizontal position						
	1	0	0	0	0	0	0	0
02	HMoiréMode 1: Separated 0: Combined	<i>HMOIRE</i> Horizontal moiré amplitude						
		0	0	0	0	0	0	0
03	B+SyncV 0: Asynchro.	<i>BREF</i> B+reference						
		1	0	0	0	0	0	0
04	Reserved							
05	Reserved							
06	BOutPol 0: Type N	Reserved						
07	BOutPh 0: H-flyback 1: H-drive	<i>VSIZ</i> Vertical size						
		1	0	0	0	0	0	0
08	EWTrHFr 0: No tracking	<i>VPOS</i> Vertical position						
		1	0	0	0	0	0	0
09	Reserved	<i>SCOR</i> S-correction						
		1	0	0	0	0	0	0
0A	Reserved	<i>CCOR</i> C-correction						
		1	0	0	0	0	0	0
0B	Reserved	<i>VMOIRE</i> Vertical moiré amplitude						
		0	0	0	0	0	0	0
0C	Reserved	<i>PCC</i> Pin cushion correction						
		1	0	0	0	0	0	0
0D	Reserved	<i>KEYST</i> Keystone correction						
		1	0	0	0	0	0	0
0E	Reserved	<i>TCC</i> Top corner correction						
		1	0	0	0	0	0	0
0F	Reserved	<i>BCC</i> Bottom corner correction						
		1	0	0	0	0	0	0
10		<i>HSIZ</i> Horizontal size						
	1	0	0	0	0	0	0	0

Table 8. I²C-bus control registers

Sad	D7	D6	D5	D4	D3	D2	D1	D0
11	Reserved	<i>PCAC Pin cushion asymmetry correction</i>						
		1	0	0	0	0	0	0
12	Reserved	<i>PARAL Parallelogram correction</i>						
		1	0	0	0	0	0	0
13	Reserved	<i>TCAC Top corner asymmetry correction</i>						
		1	0	0	0	0	0	0
14	Reserved	<i>BCAC Bottom corner asymmetry correction</i>						
		1	0	0	0	0	0	0
15	VDyCorPol 0: "U"	<i>VDC-AMP Vertical dynamic correction</i>						
		1	0	0	0	0	0	0
16	XRayReset 0: No effect 1: Reset	VSynAuto 1: On	VSynSel 0: Comp 1: Sep	SDetReset 0: No effect 1: Reset	PLL1Pump 1,1: Fastest 0,0: Slowest		PLL1InhEn 1: On	HLockEn 1: On
17	TV 0: Off ⁽⁵⁸⁾	TH 0: Off ⁽⁵⁸⁾	TVM 0: Off ⁽⁵⁸⁾	THM 0: Off ⁽⁵⁸⁾	BOHEdge 0: Falling	HBOutEn 0: Disable	VOutEn 0: Disable	BlankMode 1: Perm.
18	Reserved							
19	Reserved 0:	<i>EWSC East-West S-correction</i>						
		1	0	0	0	0	0	0
1A	Reserved 0:	<i>EWWC East-West W-correction</i>						
		1	0	0	0	0	0	0
1B	Reserved 0:	<i>HEHTG Horizontal EHT compensation gain</i>						
		0	0	0	0	0	0	0
1C	Reserved 0:	<i>VEHTG Vertical EHT compensation gain</i>						
		0	0	0	0	0	0	0
1D	Reserved 0:	<i>VSAG Vertical size after-gain</i>						
		1	1	1	0	0	0	0
1E	Reserved 0:	<i>VPOF Vertical position offset</i>						
		1	0	0	0	0	0	0
1F	ThrBIsense 0: High	BMute 0: Off	BSafeEn 0: Disable	EWTrHSize 0: Tracking	Ident 0: No effect	HLockSpeed 0: Slow	Reserved	Reserved
READ MODE (SLAVE ADDRESS = 8D)								
XX ⁽⁵⁷⁾	HLock 0: Locked 1: Not locked	VLock 0: Locked 1: Not lock.	XRayAlarm 1: On 0: Off	<i>Polarity detection</i>		<i>Sync detection</i>		
				HVPol 1: Negative	VPol 1: Negative	VExtrDet 0: Not det.	HVDet 0: Not det.	VDet 0: Not det.

Note 56: With exception of *HDUTY* and *BREF* adjustments data that can take effect instantaneously if switches *HDutySyncV* and *B+SyncV* are at 0, respectively.

Note 57: In Read Mode, the device always outputs data of the status register, regardless of sub address previously selected.

Note 58: The TV, TH, TVM and THM bits are for testing purposes and must be kept at 0 by application.

DESCRIPTION OF I²C-BUS SWITCHES AND FLAGS

Write-to bits

Sad00h/D7 - HDutySyncV

Synchronization of internal application of **H**orizontal **D**uty cycle data, buffered in I²C-bus latch, with internal discharge of **V**ertical oscillator.

- 0: Asynchronous mode, new data applied with ACK bit of I²C-bus transfer on this sub address
- 1: Synchronous mode

Sad02h/D7 - HMoiréMode

Horizontal **M**oiré characteristics.

- 0: Adapted to an architecture with EHT generated in deflection section
- 1: Adapted to an architecture with separated deflection and EHT sections

Sad03h/D7 - B+SyncV

Same as HDutySyncV, applicable for **B+** reference data

Sad06h/D7 - BOutPol

Polarity of B+ drive signal on **B**Out pin.

- 0: adapted to N type of power MOS - high level to make it conductive
- 1: adapted to P type of power MOS - low level to make it conductive

Sad07h/D7 - BOutPh

Phase of start of B+ drive signal on **B**Out pin

- 0: End of horizontal flyback or horizontal frequency divided by 2, see BOHedge bit.
- 1: With one of edges of line drive signal on **H**Out pin, selected by BOHedge bit

Sad08h/D7 - EWTrHFr

Tracking of all corrections contained in waveform on pin **E**WOut with **H**orizontal **F**requency

- 0: Not active
- 1: Active

Sad15h/D7 - VDyCorPol

Polarity of **V**ertical **D**ynamic **C**orrection waveform (parabola)

- 0: Concave (minimum in the middle of the parabola)
- 1: Convex (maximum in the middle of the parabola)

Sad16h/D0 - HLockEn

Enable of output of **H**orizontal PLL1 **L**ock/unlock status signal on pin **H**LckVBk

- 0: Disabled, vertical blanking only on the pin **H**LckVBk
- 1: Enabled

Sad16h/D1 - PLL1InhEn

Enable of **I**nhibition of horizontal **P**LL1 during extracted vertical synchronization pulse

- 0: Disabled, PLL1 is never inhibited
- 1: Enabled

Sad16h/D2 and D3- PLL1Pump

Horizontal **P**LL1 charge **P**ump current

D3	D2	Time Constant
0	0	Slowest PLL1, lowest current
1	0	Moderate Slow PLL1, low current
0	1	Moderate Fast PLL1, high current
1	1	Fastest PLL1, highest current

Sad16h/D4 - SDetReset

Reset to 0 of **S**ynchronization **D**etection flags **V**Det, **H**VDet and **V**ExtrDet of status register effected with ACK bit of I²C-bus data transfer into register containing the **S**DetReset bit. Also see description of the flags.

- 0: No effect
- 1: Reset with automatic return of the bit to 0

Sad16h/D5 - VSyncSel

Vertical **S**ynchronization input **S**election between the one extracted from composite HV signal on pin **H/HV**Syn and the one on pin **V**Syn. No effect if **V**SynAuto bit is at 1.

- 0: V. sync extracted from composite signal on **H/HV**Syn pin selected
- 1: V. sync applied on **V**Syn pin selected

Sad16h/D6 - VSyncAuto

Vertical **S**ynchronization input selection **A**utomatic mode. If enabled, the device automatically selects between the vertical sync extracted from composite HV signal on pin **H/HV**Syn and the one on pin **V**Syn, based on detection mechanism. If both are present, the one coming first is kept.

- 0: Disabled, selection done according to bit **V**SynSel
- 1: Enabled, the bit **V**SynSel has no effect

Sad16h/D7 - XRayReset

Reset to 0 of **XRay** flag of status register effected with ACK bit of I²C-bus data transfer into register containing the **XRayReset** bit. Also see description of the flag.

- 0: No effect
- 1: Reset with automatic return of the bit to 0

Sad17h/D0 - BlankMode

Blanking operation Mode.

- 0: Blanking pulse starting with detection of vertical synchronization pulse and ending with end of vertical oscillator discharge (start of vertical sawtooth ramp on the **VOut** pin)
- 1: Permanent blanking - high blanking level in composite signal on pin **HLckVBk** is permanent

Sad17h/D1 - VOutEn

Vertical Output Enable.

- 0: Disabled, **V_{offVOut}** on **VOut** pin (see [Section 6.5 Vertical section](#))
- 1: Enabled, vertical ramp with vertical position offset on **VOut** pin

Sad17h/D2 - HBOuten

Horizontal and B+ Output Enable.

- 0: Disabled, levels corresponding to “power transistor off” on **HOut** and **BOut** pins (high for **HOut**, high or low for **BOut**, depending on **BOutPol** bit).
- 1: Enabled, horizontal deflection drive signal on **HOut** pin providing that it is not inhibited by another internal event (activated **XRay** protection). B+ drive signal on **BOut** pin if not inhibited by another internal event.

Programming the bit to 1 after prior value of 0, will initiate soft start mechanism of horizontal drive and, if this is not inhibited by another internal event, also the soft start of B+ DC/DC converter controller. See also bits **BMute** and **BSafeEn**.

Sad17h/D3 - BOHEdge

If the bit **BOutPh** is at 1, selection of **Edge** of **Horizontal** drive signal to phase **B+** drive **Output** signal on **BOut** pin.

- 1: Rising edge
- 0: Falling edge

If the bit **BOutPh** is at 0, selection of signal to phase **B+** drive output on **BOut** pin:

- 1: Horizontal frequency divided by 2 signal, top of horizontal VCO
- 0: End of horizontal flyback

Sad17h/D4,D5,D6,D7 - THM, TVM, TH, TV

Test bits. They must be kept at 0 level by application S/W.

Sad1Fh/D2 - HLockSpeed

Response **Speed** of lock-to-unlock transition of H-lock component on **HLock** output and **HLock** I²C-bus flag at signal change.

- 0: Low
- 1: High

Sad1Fh/D3 - Ident

Device **Identification** bit.

If **HBOuten** is at 1, the bit has no effect.

If **HBOuten** is at 0, then

- 0: The value of Hlock status bit is 1
- 1: The value of Hlock status bit is 0

Sad1Fh/D4 - EWTrHSize

Tracking of all corrections contained in waveform on pin **EWOut** with **Horizontal Size** I²C-bus register **HSize**.

- 0: Active
- 1: Not active

Sad1Fh/D5 - BSafeEn

B+ Output Safety Enable.

- 0: Disabled
- 1: Enabled, **BOut** goes off as soon as **HLock** status of Horizontal PLL1 indicates “unlock” state. Retrieval of “lock” state will initiate soft start mechanism of DC/DC controller on **BOut** output.

Sad1Fh/D6 - BMute

B+ Output Mute.

- 0: Disabled
- 1: Enabled, **BOut** goes unconditionally off. Programming this bit back to 0 will initiate soft start mechanism of DC/DC controller on **BOut** output.

Sad1Fh/D7 - ThrBIsense

Threshold on **BIsense** input corresponding to current limitation.

- 0: High
- 1: Low

Read-out flags

SadXX/D0 - VDet⁽⁵⁹⁾

Flag indicating **Detection** of **V** synchronization pulses on **VSyn** pin.

- 0: Not detected
- 1: Detected

SadXX/D1 - HVDet⁽⁵⁹⁾

Flag indicating **Detection** of **H** or **HV** synchronization pulses applied on **H/HVSyn** pin. Once the sync pulses are detected, the flag is set and latched. Disappearance of the sync signal will not lead to reset of the flag.

- 0: Not detected
- 1: Detected.

SadXX/D2 - VExtrDet⁽⁵⁹⁾

Flag indicating **Detection** of **Extracted Vertical** synchronization signal from composite H+V signal applied on **H/HVSyn** pin.

- 0: Not detected
- 1: Detected

SadXX/D3 - VPol

Flag indicating **Polarity** of **V** synchronization pulses applied on **VSyn** pin with respect to mean level of the sync signal.

- 0: Positive
- 1: Negative

Note 59: This flag, by its value of 1, indicates an event of detection of at least one synchronization pulse since its last reset (by means of the **SDetReset** I²C-bus bit). This is to be taken into account by application S/W in a way that enough time (at least the period between 2 synchronization pulses of analyzed signal) must be provided between reset of the flag through **SDetReset** bit and validation of information provided in the flag after read-out of status register.

SadXX/D4 - HVPol

Flag indicating **Polarity** of **H** or **HV** synchronization pulses applied on **H/HVSyn** pin with respect to mean level of the sync signal.

- 0: Positive
- 1: Negative

SadXX/D5 - XRayAlarm

Alarm indicating that an event of excessive voltage has passed on **XRay** pin. Can only be reset to 0 through I²C-bus bit **XRayReset** or by power-on reset.

- 0: No excess since last reset of the bit
- 1: At least one event of excess appeared since the last reset of the bit, **HOut** inhibited

SadXX/D6 - VLock

Status of “**Locking**” or stabilizing of **Vertical** oscillator amplitude to an internal reference by AGC regulation loop.

- 0: Locked (amplitude stabilized)
- 1: Not locked (amplitude non-stabilized)

SadXX/D7 - HLock

Lock status of **Horizontal** PLL1.

- 0: Locked
- 1: Not locked

See also bit **Ident** (Sad1Fh/D3)

9 OPERATING DESCRIPTION

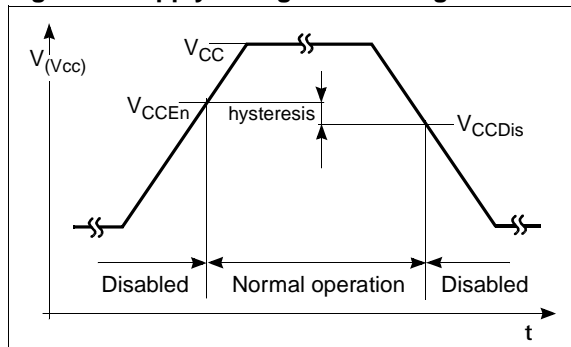
9.1 Supply and control

9.1.1 Power supply and voltage references

The device is designed for a typical value of power supply voltage of 12 V.

In order to avoid erratic operation of the circuit at power supply ramp-up or ramp-down, the value of V_{CC} is monitored. See Figure 1 and electrical specifications. At switch-on, the device enters a "normal operation" as the supply voltage exceeds V_{CCEn} and stays there until it decreases below V_{CCDis} . The two thresholds provide, by their difference, a hysteresis to bridge potential noise. Outside the "normal operation", the signals on $HOut$, $BOut$ and $VOut$ outputs are inhibited and the I²C-bus interface is inactive (high impedance on SDA , SCL pins, no ACK), all I²C-bus control registers being reset to their default values (see Chapter 8 - page 25). The stop of $HOut$ and $BOut$ drive signals when the V_{CC} falls from normal operation below V_{CCDis} is not instantaneous. It is only a trigger point of Soft Stop mechanism (see Subsection 9.3.7- page 35).

Figure 1. Supply voltage monitoring



9.2 Synchronization processor

9.2.1 Synchronization signals

The device has two inputs for TTL-level synchronization signals, both with hysteresis to avoid erratic detection and with a pull-down resistor. On $H/HVSyn$ input, pure horizontal or composite horizontal/vertical signal is accepted. On $VSyn$ input, only pure vertical sync. signal is accepted. Both positive and negative polarities may be applied on either input, see Figure 2. Polarity detector and programmable inverter are provided on each of the two inputs. The signal applied on $H/HVSyn$ pin, after polarity treatment, is directly lead to horizontal

Internal thresholds in all parts of the circuit are derived from a common internal reference supply V_{RefO} that is lead out to $RefOut$ pin for external filtering against ground as well as for external use with load currents limited to I_{RefO} . The filtering is necessary to minimize interference in output signals, causing adverse effects like e.g. jitter.

9.1.2 I²C-bus control

The I²C-bus is a 2 line bidirectional serial communication bus introduced by Philips. For its general description, refer to corresponding Philips I²C-bus specification.

This device is an I²C-bus slave, compatible with fast (400kHz) I²C-bus protocol, with write mode slave address of 8Ch (read mode slave address 8Dh). Integrators are employed at the SCL (Serial Clock) input and at the input buffer of the SDA (Serial Data) input/output to filter off the spikes up to 50ns.

The device supports multiple data byte messages (with automatic incrementing of the I²C-bus subaddress) as well as repeated Start Condition for I²C-bus subaddress change inside the I²C-bus messages. All I²C-bus registers with specified I²C-bus subaddress are of WRITE ONLY type, whereas the status register providing a feedback information to the master I²C-bus device has no attributed I²C-bus subaddress and is of READ ONLY type. The master I²C-bus device reads this register sending directly, after the Start Condition, the READ device I²C-bus slave address (8Dh) followed by the register read-out, NAK (No Acknowledge) signal and the Stop Condition.

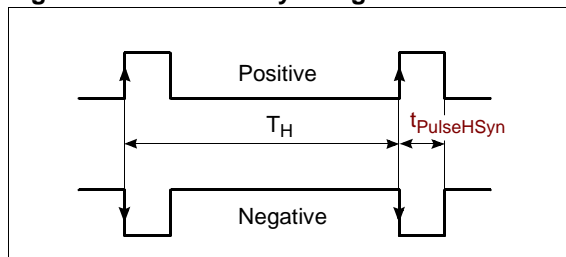
For the I²C-bus control register map, refer to Chapter 8 - page 25.

part and to an extractor of vertical sync. pulses, working on principle of integration, see Figure 3. The vertical sync. signal applied to the vertical deflection processor is selected between the signal extracted from the composite signal on $H/HVSyn$ input and the one applied on $VSyn$ input. The selector is controlled by $VSynSel$ I²C-bus bit.

Besides polarity detection, the device is capable of detecting presence of sync. signals on each of the inputs and at the output of vertical sync. extractor. The information from all detectors is provided in the I²C-bus status register (5 flags: $VDet$, $HVDet$,

VEextrDet, VPol, HVPol). The device is equipped with an automatic mode (switched on or off by VSyncAuto I²C-bus bit) that also uses the detection information.

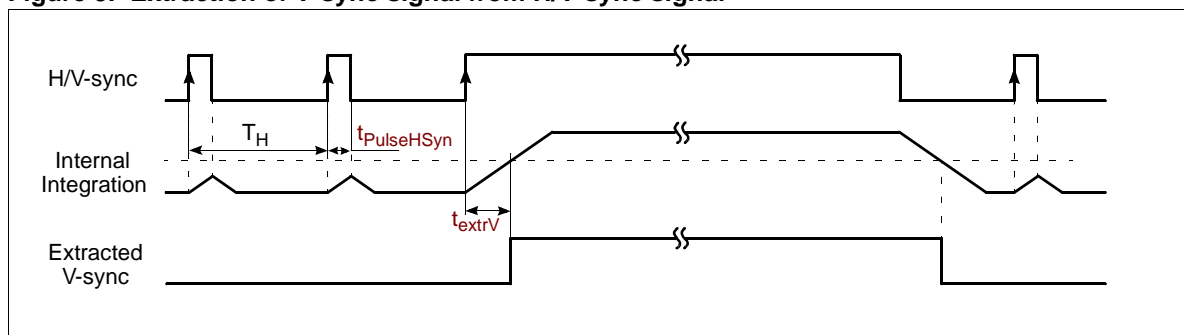
Figure 2. Horizontal sync signal



9.2.2 Sync. presence detection flags

The sync. signal presence detection flags in the status register (VDet, HVDet, VEextrDet) do not show in real time the presence or absence of corresponding sync. signal. They are latched to 1 as soon as a single sync. pulse is detected. In order to reset them to 0 (all at once), a 1 must be written into SDetReset I²C-bus bit, the reset action taking effect with ACK bit of the I²C-bus transfer to the register containing SDetReset bit. The detection circuits are ready to capture another event (pulse). See [Note 59](#).

Figure 3. Extraction of V-sync signal from H/V-sync signal



9.2.3 MCU controlled sync. selection mode

I²C-bus bit VSyncAuto is set to 0. The MCU reads the polarity and signal presence detection flags, after setting the SDetReset bit to 1 and an appropriate delay, to obtain a true information of the signals applied, reads and evaluates this information and controls the vertical signal selector accordingly. The MCU has no access to polarity inverters, they are controlled automatically.

See also chapter [Chapter 8 - page 25](#).

9.2.4 Automatic sync. selection mode

I²C-bus bit VSyncAuto is set to 1. In this mode, the device itself controls the I²C-bus bits switching the polarity inverters (HVPol, VPol) and the vertical sync. signal selector (VSyncSel), using the information provided by the detection circuitry. If both extracted and pure vertical sync. signals are present, the one already selected is maintained. No intervention of the MCU is necessary.

9.3 Horizontal section

9.3.1 General

The horizontal section consists of two PLLs with various adjustments and corrections, working on horizontal deflection frequency, then phase shifting and output driving circuitry providing H-drive signal on **HOut** pin. Input signal to the horizontal section is output of the polarity inverter on **H/HVSyn** input. The device ensures automatically that this polarity be always positive.

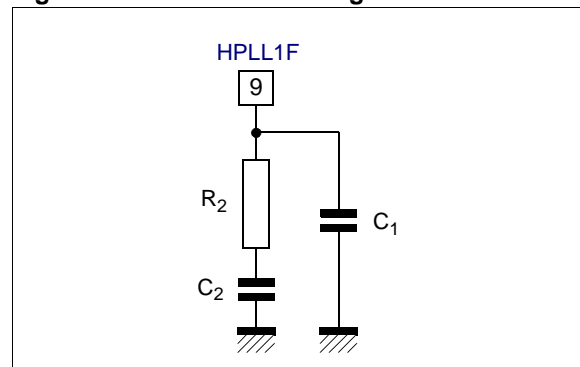
9.3.2 PLL1

The PLL1 block diagram is in [Figure 5](#). It consists of a voltage-controlled oscillator (VCO), a shaper with adjustable threshold, a charge pump with inhibition circuit, a frequency and phase comparator and timing circuitry. The goal of the PLL1 is to make the VCO ramp signal match in frequency the sync. signal and to lock this ramp in phase to the sync. signal. On the screen, this offset results in the change of horizontal position of the picture. The loop, by tuning the VCO accordingly, gets and maintains in coincidence the rising edge of input sync. signal with signal REF1, deriving from the VCO ramp by a comparator with threshold adjustable through **HPOS** I²C-bus control. The coincidence is identified and flagged by lock detection circuit on pin **HLckVBk** as well as by **HLock** I²C-bus flag.

The charge pump provides positive and negative currents charging the external loop filter on **HPLL1F** pin. The loop is independent of the trailing edge of sync. signal and only locks to its leading edge. By design, the PLL1 does not suffer from any dead band even while locked. The speed of the PLL1 depends on current value provided by the charge pump. While not locked, the current is very low, to slow down the changes of VCO frequency and thus protect the external power components at

sync. signal change. In locked state, the currents are much higher, four different values being selectable via **PLL1Pump** I²C-bus bits to provide a means to control the PLL1 speed by S/W. Lower value make the PLL1 slower, but more stable. Higher values make it faster and less stable. In general, the PLL1 speed should be higher for high deflection frequencies. The response speed and stability (jitter level) depend on the choice of external components making up the loop filter. A "CRC" filter is generally used (see [Figure 4](#)).

Figure 4. H-PLL1 filter configuration



The PLL1 is internally inhibited during extracted vertical sync. pulse (if any) to avoid taking into account missing or wrong pulses on the phase comparator. Inhibition is obtained by forcing the charge pump output to high impedance state. The inhibition mechanism can be disabled through **PLL1InhEn** I²C-bus bit.

The [Figure 7](#), in its upper part, shows the position of the VCO ramp signal in relation to input sync. pulse for three different positions of adjustment of horizontal position control **HPOS**.

9.3.4 PLL2

The goal of the PLL2 is, by means of phasing the signal driving the power deflection transistor, to lock the middle of the horizontal flyback to a certain threshold of the VCO sawtooth. This internal threshold is affected by geometry phase corrections, like e.g., parallelogram. The PLL2 is fast enough to be able to follow the dynamism of phase modulation, this speed is strongly related to the value of the capacitor on **HPLL2C**. The PLL2 control current (see [Figure 7](#)) is significantly increased during discharge of vertical oscillator (during vertical retrace period) to be able to make up for the difference of dynamic phase at the bottom and at the top of the picture. The PLL2 control current is integrated on the external filter on pin **HPLL2C** to obtain smoothed voltage, used, in comparison with VCO ramp, as a threshold for H-drive rising edge generation.

As both leading and trailing edges of the H-drive signal in the [Figure 7](#) must fall inside the rising part of the VCO ramp, an optimum middle position of the threshold has been found to provide enough margin for horizontal output transistor storage time as well as for the trailing edge of H-drive signal with maximum duty cycle. Yet, the constraints thereof must be taken into account while considering the application frequency range and H-flyback duration. The [Figure 7](#) also shows regions for rising and falling edges of the H-drive signal on **HOut** pin. As it is forced high during the H-flyback pulse and low during the VCO discharge period, no edge during these two events takes effect.

The flyback input configuration is in [Figure 8](#).

9.3.5 Dynamic PLL2 phase control

The dynamic phase control of PLL2 is used to compensate for picture asymmetry versus vertical axis across the middle of the picture. It is done by modulating the phase of the horizontal deflection with respect to the incoming video (synchronization). Inside the device, the threshold $V_{S(0)}$ is compared with the VCO ramp, the PLL2 locking the middle of H-flyback to the moment of their match. The dynamic phase is obtained by modulation of the threshold by correction waveforms. Refer to [Figure 14](#) and [Chapter 7 - page 21](#). The correction waveforms have no effect in vertical middle of the screen (for middle vertical position). As they are summed, their effect on the phase tends to reach maximum span at top and bottom of the picture. As all the components of the resulting correction waveform (linear for parallelogram correction, pa-

rabola of 2nd order for Pin cushion asymmetry correction and half-parabolas of 4th order for corner corrections independently at the top and at the bottom) are generated from the output vertical deflection drive waveform, they all track with real vertical amplitude and position, thus being fixed on the screen. Refer to [Chapter 8 - page 25](#) for details on I²C-bus controls.

Figure 7. Horizontal timing diagram

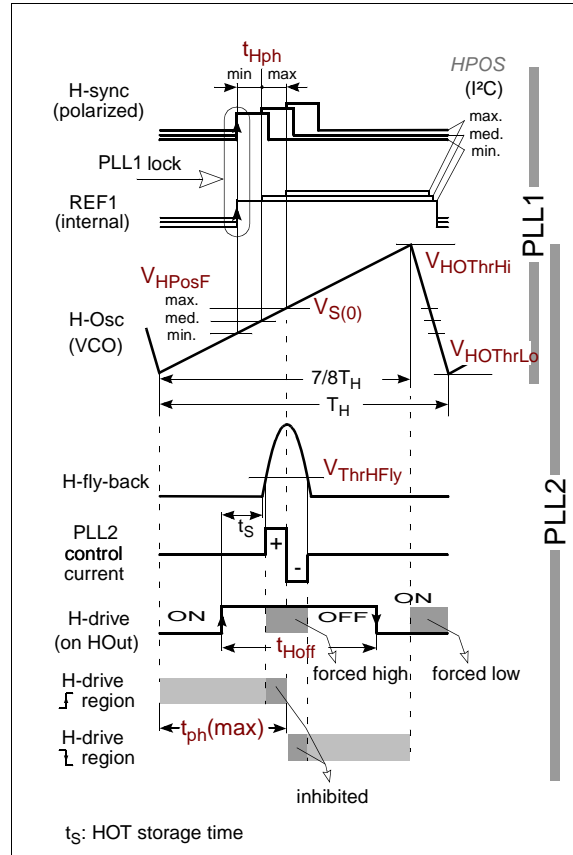
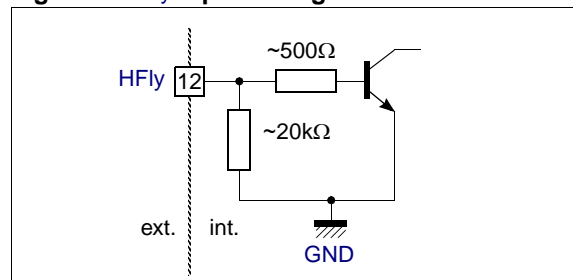


Figure 8. HFly input configuration



9.3.6 Output Section

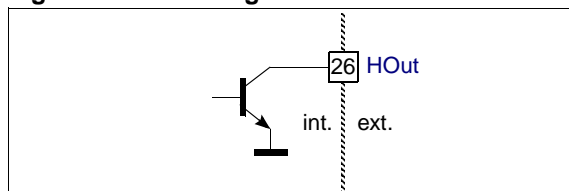
The H-drive signal is inhibited (high level) during flyback pulse, and also when V_{CC} is too low, when X-ray protection is activated (XRyAlarm I²C-bus flag set to 1) and when I²C-bus bit HBOutEn is set to 0 (default position).

The duty cycle of the H-drive signal is controlled via I²C-bus register HDUTY. This is overruled during soft-start and soft-stop procedures (see Section 9.3.7 and Figure 10).

The PLL2 is followed by a rapid phase shifting which accepts the signal from H-moiré canceller (see Section 9.3.8)

The output stage consists of a NPN bipolar transistor, the collector of which is routed to HOut pin (see Figure 9).

Figure 9. HOut configuration



9.3.7 Soft-start and soft-stop on H-drive

The soft-start and soft-stop procedure is carried out at each switch-on or switch-off of the H-drive signal, either via HBOutEn I²C-bus bit or after reset of XRyAlarm I²C-bus flag, to protect external power components. By its second function, the external capacitor on pin HPosF is used to time out this procedure, during which the duty cycle of H-drive signal starts at its maximum (t_{Hoff} for soft start/stop in electrical specifications) and slowly decreases to the value determined by the control I²C-bus register HDUTY (vice versa at soft-stop). This is controlled by voltage on pin HPosF. In case of supply voltage switch off, the transients on HOut and BOut have different characteristics. See Figure 10, Figure 11 and Section 9.8.1.

9.3.8 Horizontal moiré cancellation

The horizontal moiré canceller is intended to blur a potential beat between the horizontal video pixel period and the CRT pixel width, which causes visible moiré patterns in the picture.

It introduces a microscopic indent on horizontal scan lines by injecting little controlled phase shifts to output circuitry of the horizontal section. Their amplitude is adjustable through HMOIRE I²C-bus control.

The behaviour of horizontal moiré is to be optimized for different deflection design configurations using HMoiréMode I²C-bus bit. This bit is to be kept at 0 for common architecture (B+ and EHT common regulation) and at 1 for separated architecture (B+ and EHT each regulated separately). The maximum amplitude adjustable through HMOIRE I²C-bus control is optimized according to selection by HMoiréMode I²C-bus bit: larger when B+ and EHT are each regulated separately, smaller when B+ and EHT are common regulation.

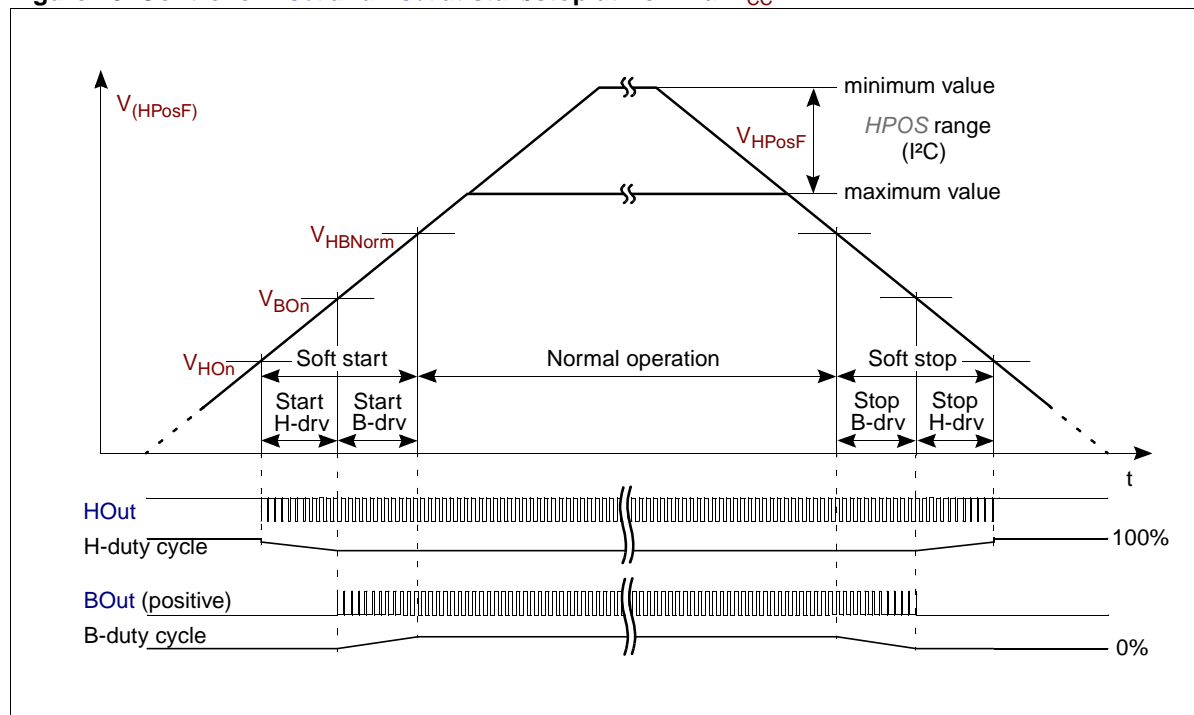
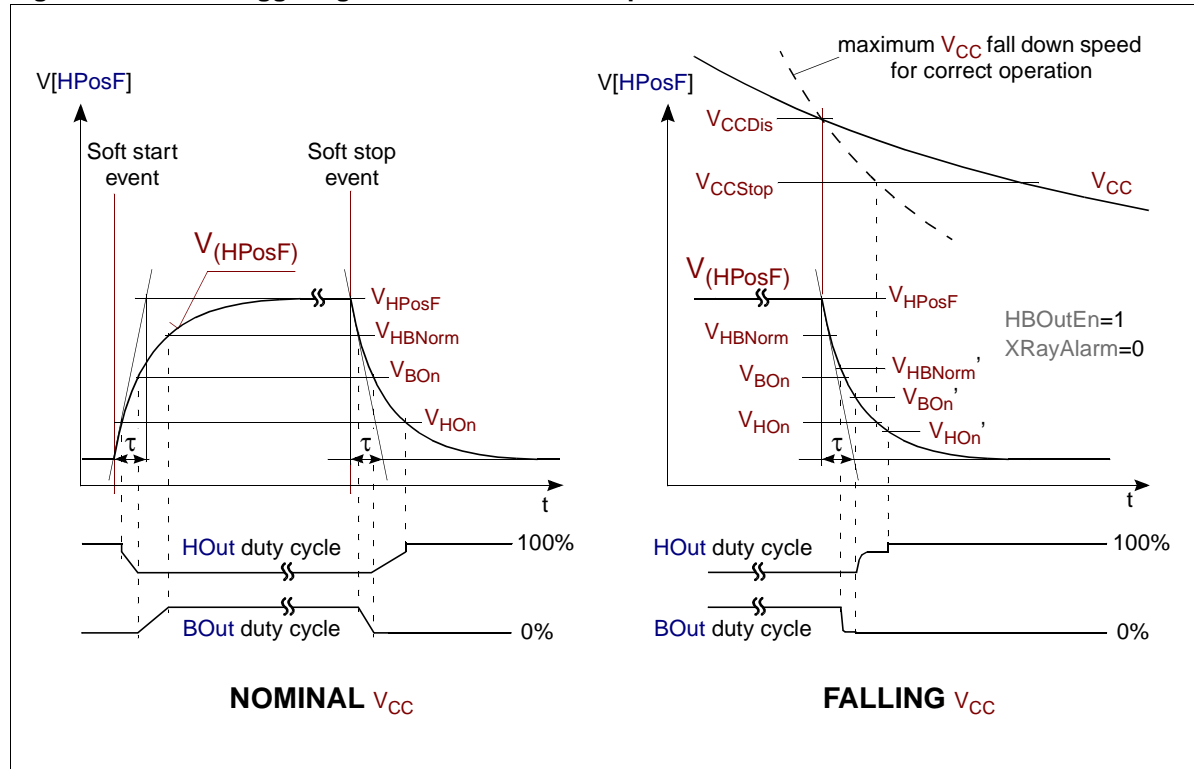
Figure 10. Control of HOut and BOut at start/stop at nominal V_{CC} 

Figure 11. Events triggering Soft start and Soft stop



9.4 Vertical section

9.4.1 General

The goal of the vertical section is to drive vertical deflection output stage. It delivers a sawtooth waveform with an amplitude independent of deflection frequency, on which vertical linearity corrections of C- and S-type are superimposed (see Chapter 7 - page 21).

Block diagram is in Figure 12. The sawtooth is obtained by charging an external capacitor on pin **VCap** with controlled current and by discharging it via transistor Q1. This is controlled by the CONTROLLER. The charging starts when the voltage across the capacitor drops below V_{VOB} threshold. The discharging starts either when it exceeds V_{VOT} threshold (free run mode) or a short time after arrival of synchronization pulse. This time is necessary for the AGC loop to sample the voltage at the top of the sawtooth. The V_{VOB} reference is routed out onto **VOscF** pin in order to allow for further filtration.

The charging current influences amplitude of the sawtooth. Just before the discharge, the voltage across the capacitor on pin **VCap** is sampled and compared to V_{VOTref} . The comparison error voltage is stored on a storage capacitor connected on pin **VAGCCap**. This voltage tunes gain of the transconductance amplifier providing the charging current in the next vertical period. Speed of this AGC loop depends on the storage capacitance on pin **VAGCCap**. The **VLock** I²C-bus flag is set to 1 when the loop is stabilized, i.e. when the tops of sawtooth on pin **VCap** match V_{VOT} value. On the screen, this corresponds to stabilized vertical size of picture. After a change of frequency on the sync. input, the stabilization time depends on the frequency difference and on the capacitor value. The lower its value, the shorter the stabilization time, but on the other hand, the lower the loop stability. A practical compromise is a capacitance of 470nF. The leakage current of this capacitor results in difference in amplitude between low and high frequencies. The higher its parallel resistance $R_L(VAGCCap)$, the lower this difference.

When the synchronization pulse is not present, the charging current is fixed. As a consequence, the free-running frequency $f_{VO(0)}$ only depends on the value of the capacitor on pin **VCap**. It can be roughly calculated using the following formula

$$f_{VO(0)} = \frac{150nF}{C_{(VCap)}} \cdot 100Hz$$

The frequency range in which the AGC loop can regulate the amplitude also depends on this capacitor.

The vertical sawtooth with regulated amplitude is lead to amplitude control stage. The discharge exponential is replaced by V_{VOB} level, which, under control of the CONTROLLER, creates a rapid falling edge and a flat part before beginning of new ramp.

The AGC output signal passes through gain and position adjustment stages controlled through **VSIZE** and **VPOS** I²C-bus registers. The resulting signal serves as input to all geometry correction circuitry including EW-drive signal, horizontal phase modulation and dynamic correction outputs.

9.4.2 S and C corrections

For the sake of vertical picture linearity, the S- and C-corrections are now superimposed on the linear ramp signal. They both track with **VSIZE** and **VPOS** adjustments to ensure unchanged linearity on the screen at changes of vertical size or vertical position. As these corrections are not included in the AGC loop, their adjustment via **CCOR** and **SCOR** I²C-bus registers, controlling shape of vertical output sawtooth affects by principle its peak-to-peak amplitude. However, this stage is conceived in a way that the amplitude be independent of these adjustments if **VSIZE** and **VPOS** registers are set to their medium values.

9.4.3 Vertical breathing compensation

The signal provided with the linearity corrections is amplitude affected in a gain control stage, ruled by the voltage on **VEHTIn** input and its I²C-bus control **VEHTG**.

9.4.4 Vertical after-gain and offset control

Another gain control is applied via **VSAG** I²C-bus register. Then an offset is added, its amount corresponding to **VPOF** I²C-bus register value. These two controls result in size and position changes with no effect on shape of output vertical sawtooth or any geometry correction signal.

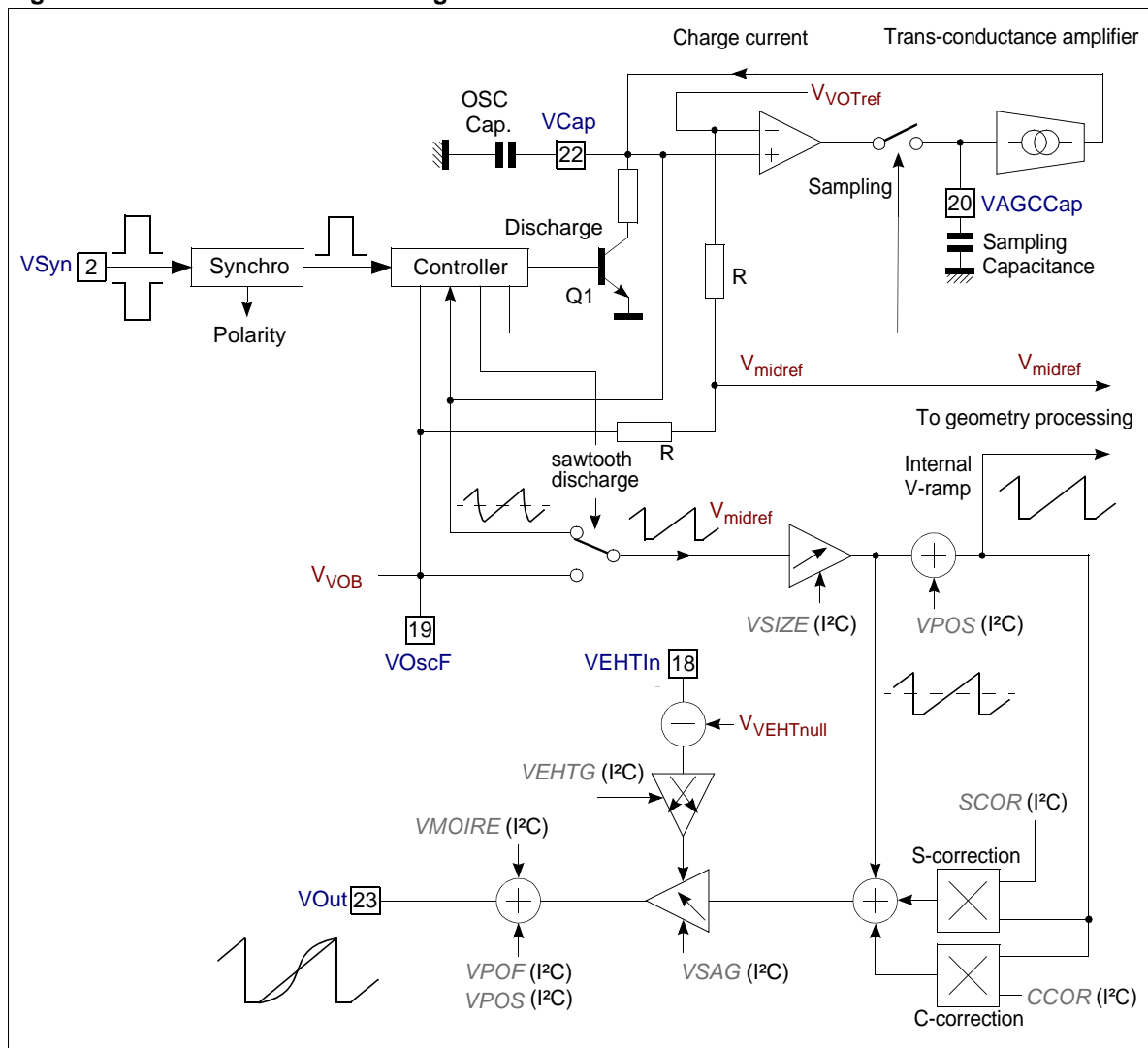
9.4.5 Vertical moiré

To blur potential moiré patterns due to interaction of deflection lines with CRT mask grid, the picture position is to be slightly alternated at frame frequency. For this purpose, a square waveform at half-frame frequency is superimposed on the output waveform. Its amplitude is adjustable through *VMOIRE* I²C-bus control.

9.4.6 Biasing of vertical booster

The biasing voltage for external DC-coupled vertical power amplifier is to be derived from V_{RefO} voltage provided on pin **RefOut**, using a resistor divider, this to ensure the same temperature drift of mean (DC) levels on both differential inputs and to compensate for spread of V_{RefO} value (and so mean output value) between particular devices.

Figure 12. Vertical section block diagram



9.5 EW drive section

The goal of the EW drive section is to provide, on pin **EWOut**, a waveform which, used by an external DC-coupled power stage, serves to compensate for those geometry errors of the picture that are symmetric versus vertical axis across the middle of the screen.

The waveform consists of an adjustable DC value, corresponding to horizontal size, a parabola of 2nd order for "pin cushion" correction, a linear for "keystone" correction, independent half-parabolas of 4th order for top and bottom corner corrections, S-shape for "S" correction and W shape for "W" correction. All of them are adjustable via I²C-bus, see [Chapter 8 - page 25](#).

Refer to [Figure 14](#), [Figure 15](#) and chapter [Chapter 7 - page 21](#). The adjustments of these correction waveforms have no effect in the middle of the vertical scan period (if the **VPOS** control is adjusted to its medium value). As they are summed, the resulting waveform tends to reach its maximum span at top and bottom of the picture. The voltage at the **EWOut** is top and bottom limited (see parameter **V_{EW}**). According to [Figure 15](#), especially the bottom limitation seems to be critical for maximum horizontal size (minimum DC). Actually it is not critical since the parabola component must always be applied to obtain a picture without pin cushion distortion. As all the components of the resulting correction waveform are generated from an internal linear vertical sawtooth waveform bearing **VSIZE** and **VPOS** adjustments, they all track with vertical amplitude and position, thus being fixed vertically on the screen. They are not affected by C- and S-cor-

rections, by prescale adjustments (**VSAG** and **VPOF**), by vertical breathing compensation and by vertical moire cancellation. The sum of components other than DC is conditionally affected by value in **HSIZE** I²C-bus control in reversed sense. Refer to electrical specifications for value. This tracking with **HSIZE** can be switched off by **EWTrHSize** I²C-bus bit. The DC value, adjusted via **HSIZE** control, is also affected by voltage on **HEHTIn** input, thus providing a horizontal breathing compensation. The effect of this compensation is controlled by **HEHTG**. The resulting waveform is conditionally multiplied with voltage on **HPLL1F**, which depends on frequency. Refer to electrical specifications for values. This tracking with frequency provides a rough compensation of variation of picture geometry with frequency and allows to fix the adjustment ranges of I²C-bus controls throughout the operating range of horizontal frequencies. It can be switched off by **EWTrHFr** I²C-bus bit (off by default). The functionality is explained in [Figure 13](#). The upper part gives the influence on DC component, the lower part on AC component, showing also the tracking with **HSIZE**. Grey zones give the total span of breathing correction using the whole range of input operating voltage on **HEHTIn** input and whole range of adjustment of **HEHTG** register.

The EW waveform signal is buffered by an NPN emitter follower, the emitter of which is directly routed to **EWOut** output. It is internally biased (see electrical specifications for current value).

Figure 13. Tracking of EWOut signal with frequency

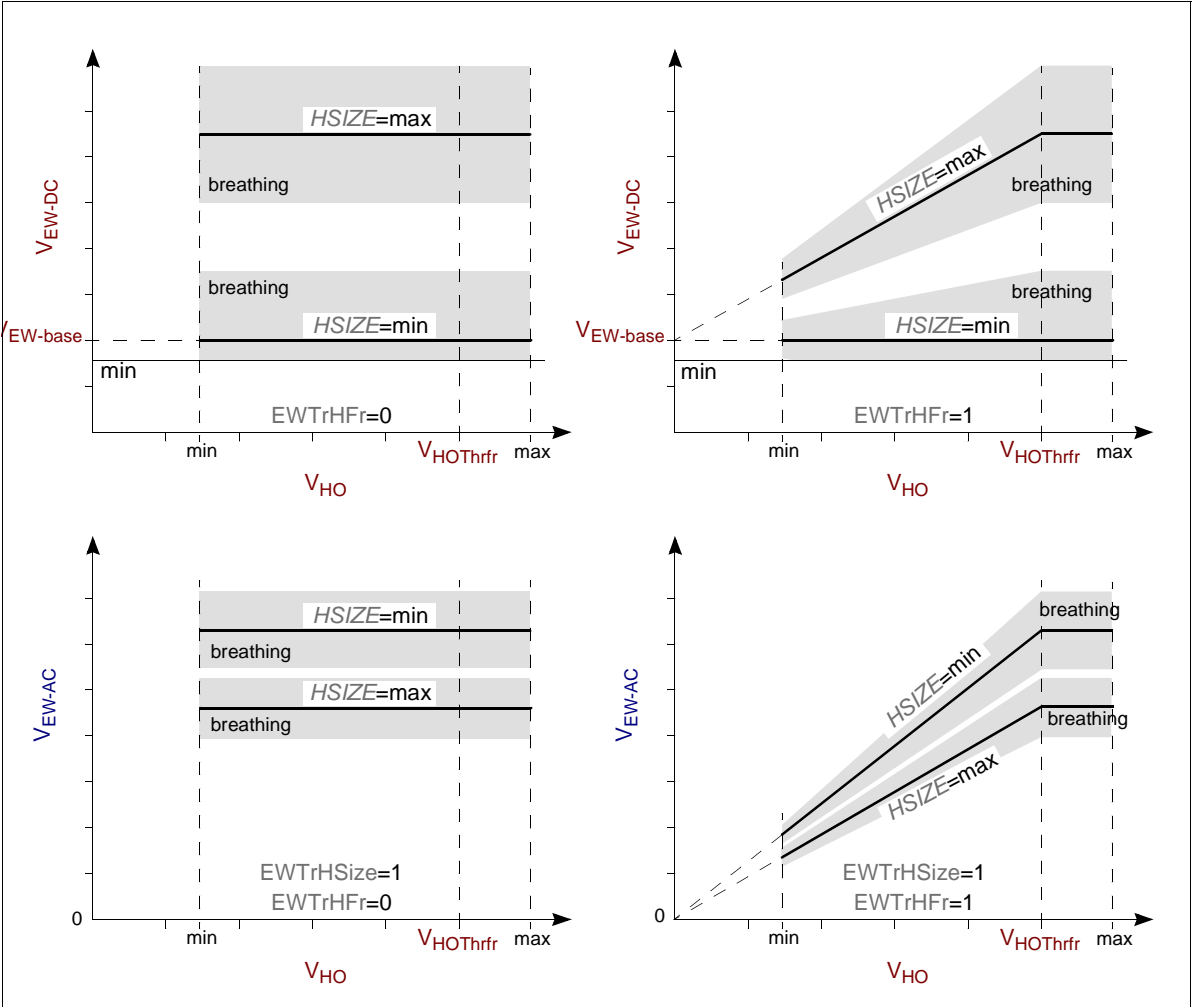
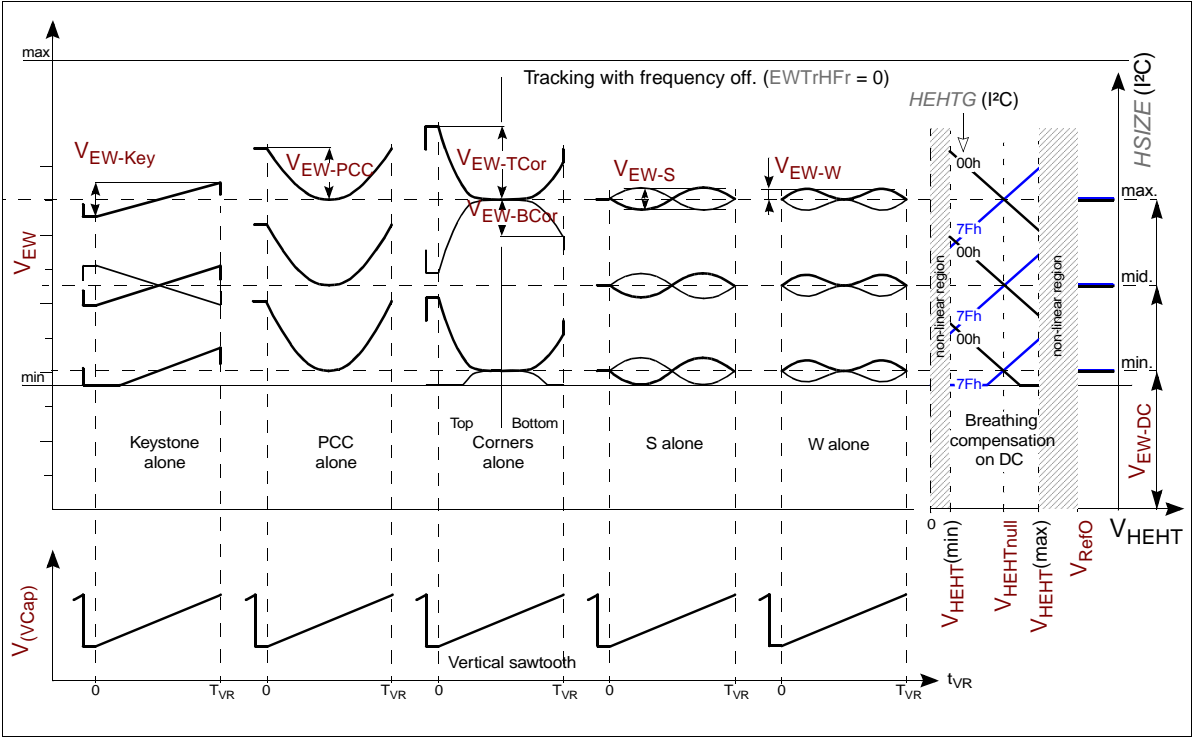


Figure 15. EWOut output waveforms



9.6 Dynamic correction outputs section

9.6.1 Vertical dynamic correction output VDyCor

A parabola at vertical deflection frequency is available on pin **VDyCor**. Its amplitude is adjustable via **VDC-AMP** I²C-bus control and polarity controlled via **VDyCorPol** I²C-bus bit. It tracks with real vertical amplitude and position. It is not affected by C-

and S-corrections or breathing compensation. It does not track with *Vertical size after-gain* (**Sad1Dh**) nor with *Vertical position offset* (**Sad1Eh**) adjustments.

The use of both correction waveforms is up to the application (e.g. dynamic focus, dynamic brightness control).

9.7 DC/DC controller section

The section is designed to control a switch-mode DC/DC converter. A switch-mode DC/DC converter generates a DC voltage from a DC voltage of different value (higher or lower) with little power losses. The DC/DC controller is synchronized to horizontal deflection frequency to minimize potential interference into the picture.

Its operation is similar to that of standard UC3842.

The schematic diagram of the DC/DC controller is in [Figure 16](#). The **BOut** output controls an external switching circuit (a MOS transistor) delivering pulses synchronized on horizontal deflection frequency, the phase of which depends on H/W and I²C-bus configuration. See the table at the end of this chapter. Their duration depends on the feedback provided to the circuit, generally a copy of DC/DC converter output voltage and a copy of current passing through the DC/DC converter circuitry (e.g. current through external power component). The polarity of the output can be controlled by **BOutPol** I²C-bus bit. A NPN transistor open-collector is routed out to the **BOut** pin.

During the operation, a sawtooth is to be found on pin **BISense**, generated externally by the application. According to **BOutPh** I²C-bus bit, the R-S flip-flop is set either at H-drive signal edge (rising or falling, depending on **BOHedge** I²C-bus bit), or a certain delay (**tBTrigDel**) after middle of H-flyback, or at horizontal frequency divided by two (phase corresponding to **V_{HOThrHi}** on the VCO ramp). The output is set On at the end of the short pulse generated by the monostable trigger.

Timing of reset of the R-S flip-flop affects duty cycle of the output square signal and so the energy transferred from DC/DC converter input to its output. A reset edge is provided by comparator C2 if the voltage on pin **BISense** exceeds the internal threshold **V_{ThrBIsCurr}**. This represents current limitation if a voltage proportional to the current through the power component or deflection stage is available on pin **BISense**. This threshold is affected by voltage on pin **HPosF**, which rises at soft start and descends at soft stop. This ensures self-contained soft control of duty cycle of the output signal on pin

BOut. Refer to [Figure 10](#). Another condition for reset of the R-S flip-flop, OR-ed with the one described before, is that the voltage on pin **BISense** exceeds the voltage **V_{C2}**, which depends on the voltage applied on input **BRegIn** of the error amplifier O1. The two voltages are compared, and the reset signal generated by the comparator C1. The error amplifier amplifies (with a factor defined by external components) the difference between the input voltage proportional to DC/DC converter output voltage and internal reference **V_{BReg}**. The internal reference and so the output voltage is I²C-bus adjustable by means of **BREF** I²C-bus control.

Both step-up (DC/DC converter output voltage higher than its input voltage) and step-down (output voltage lower than input) can be built.

9.7.1 Synchronization of DC/DC controller

For sake of application flexibility, the output drive signal on **BOut** pin can be synchronized with one of four events in [Table 9](#). For the first line case, the synchronization instant is every second top of horizontal VCO saw tooth. See [Figure 7](#).

9.7.2 Soft-start and soft-stop on B-drive

The soft-start and soft-stop procedure is carried out at each switch-on or switch-off of the B-drive signal, either via **HBOuten** I²C-bus bit or after reset of **XRayAlarm** I²C-bus flag, to protect external power component. See [Figure 10](#) and sub chapter [Safety functions](#) on [page 45](#).

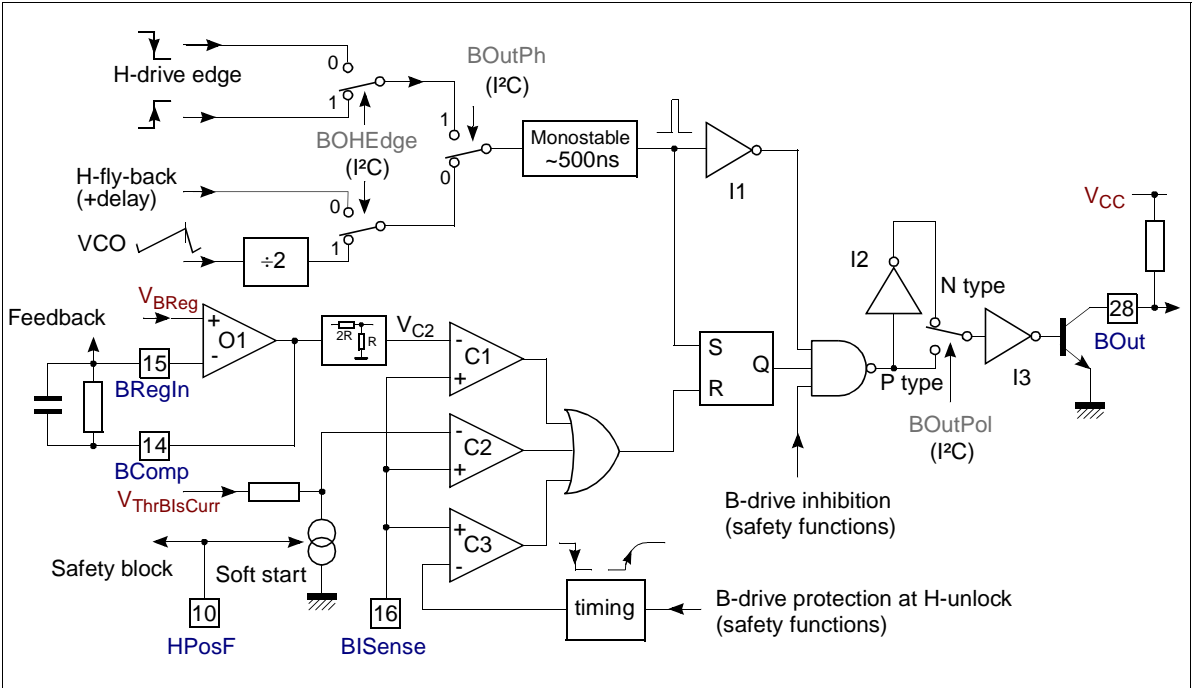
The drive signal on **BOut** pin can be switched off alone by means of **BMute** I²C-bus bit, without switching off the drive signal on pin **HOut**. The switch-off is quasi-immediate, without the soft-stop procedure. At switching back on, the soft-start of the DC/DC controller is performed, timed by an internal timing circuit, see [Figure 16](#).

When **BSafeEn** I²C-bus bit is enabled, the drive signal on **BOut** pin will go off as soon as the horizontal PLL1 indicates unlocked state, without the soft-stop. Resuming of locked state will initiate the soft-start mechanism of the DC/DC controller, timed by an internal timing circuit.

Table 9. IDC/DC controller Off-to-On edge timing

BOutPh (Sad07h/D7)	BOHEdge (Sad17h/D3)	Timing of Off-to-On transition on BOut output
0	1	VCO ramp top at Horizontal frequency divided by two
0	0	Middle of H-flyback plus $t_{BTrigDel}$
1	0	Falling edge of H-drive signal
1	1	Rising edge of H-drive signal

Figure 16. DC/DC converter controller block diagram



9.8 Miscellaneous

9.8.1 Safety functions

The safety functions comprise supply voltage monitoring with appropriate actions, soft start and soft stop features on H-drive and B-drive signals on **HOut** and **BOut** outputs, B-drive cut-off at unlock condition and X-ray protection.

For supply voltage supervision, refer to subsection 9.1.1 and Figure 1. A schematic diagram putting together all safety functions and composite PLL1 lock and V-blanking indication is in Figure 17.

9.8.1.1 Soft start and soft stop function

For soft start and soft stop features for H-drive and B-drive signal, refer to subsection 9.3.7 and subsection 9.7, respectively. See also the Figure 10 and Figure 11. Regardless why the H-drive or B-drive signal are switched on or off (I²C-bus command, power up or down, X-ray protection), the signals always phase-in and phase-out in the way drawn in the figures, the first to phase-in and last to phase-out being the H-drive signal, which is to better protect the power stages at abrupt changes like switch-on and off. The timing of phase-in and phase-out depends on the capacitance connected to **HPosF** pin which is virtually unlimited for this function. However, as it has a dual function (see subsection 9.3.2), a compromise thereof is to be found.

The soft stop at power down condition can be considered as a special case. As at this condition the thresholds V_{HOn} , V_{BOn} and V_{HBNorm} depend on the momentary level of supply voltage (marked V_{HOn}' , V_{BOn}' , V_{HBNorm}' in Figure 11), the timing of soft stop mechanism depends, apart from the capacitance on **HPosF**, also on the falling speed of supply voltage. The device is capable of performing a correct soft stop sequence providing that, at the moment the supply voltage reaches V_{CCStop} , the voltage on **HPosF** has already fallen below V_{HOn} (Section 9.8).

9.8.1.2 B-drive cut-off at unlock condition

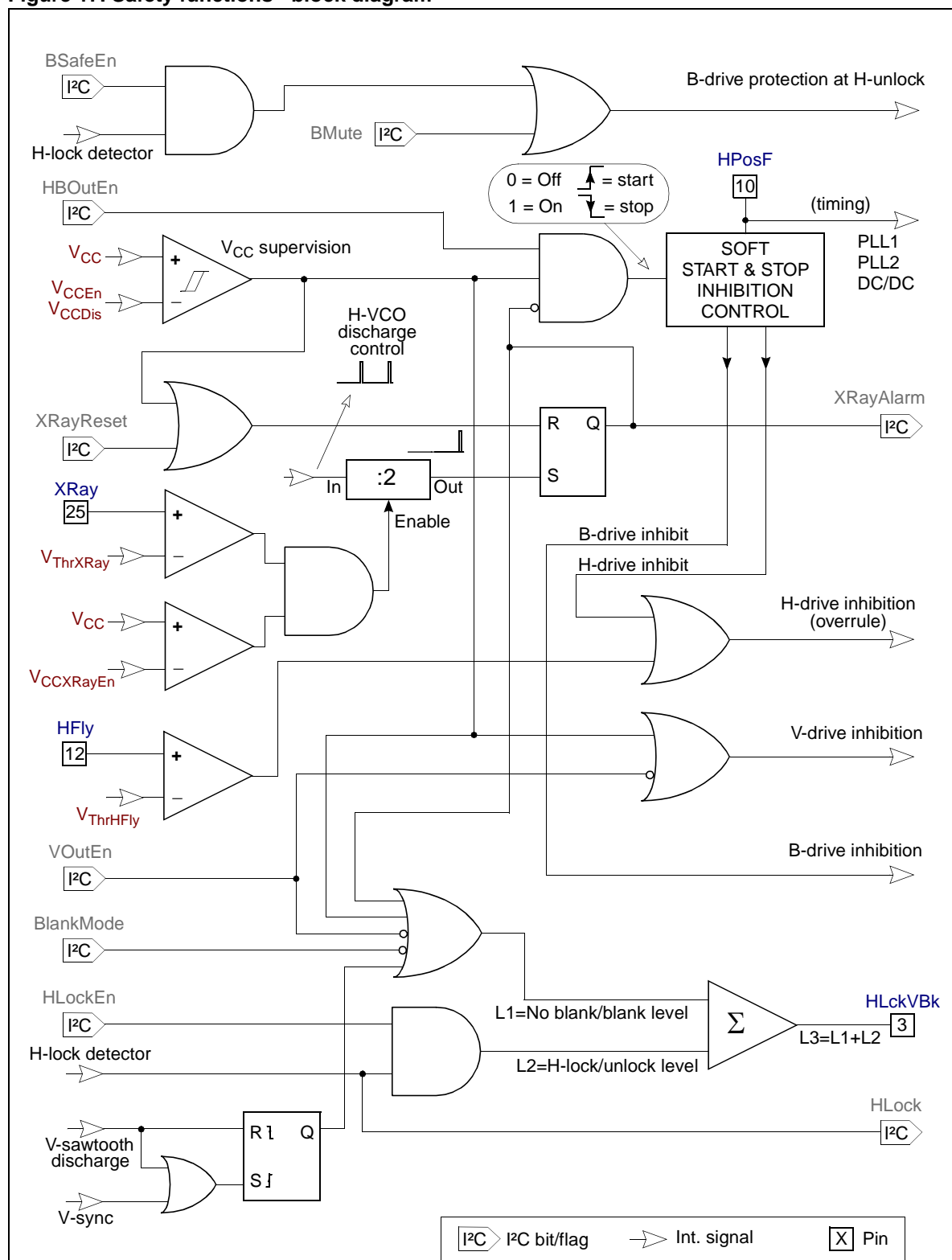
This function is described in subsection 9.7.2.

9.8.1.3 X-ray protection

The X-ray protection is activated if the voltage level on **XRay** input exceeds $V_{ThrXRay}$ threshold and if the V_{CC} is higher than the voltage level $V_{CCXRayEn}$. As a consequence, the H-drive and B-drive signals on **HOut** and **BOut** outputs are inhibited (switched off) after a 2-horizontal deflection line delay provided to avoid erratic excessive X-ray condition detection at short parasitic spikes. The **XRayAlarm** I²C-bus flag is set to 1 to inform the MCU.

This protection is latched; it may be reset either by V_{CC} drop or by I²C-bus bit **XRayReset** (see Chapter 8 - page 25).

Figure 17. Safety functions - block diagram



9.8.2 Composite output HLckVBk

The composite output HLckVBk provides, at the same time, information about lock state of PLL1 and early vertical blanking pulse. As both signals have two logical levels, a four level signal is used to define the combination of the two. Schematic diagram putting together all safety functions and composite PLL1 lock and V-blanking indication is in Figure 17, the combinations, their respective levels and the HLckVBk configuration in Figure 18.

The early vertical blanking pulse is obtained by a logic combination of vertical synchronization pulse and pulse corresponding to vertical oscillator discharge. The combination corresponds to the drawing in Figure 18. The blanking pulse is started with

the leading edge of any of the two signals, whichever comes first. The blanking pulse is ended with the trailing edge of vertical oscillator discharge pulse. The device has no information about the vertical retrace time. Therefore, it does not cover, by the blanking pulse, the whole vertical retrace period. By means of BlankMode I²C-bus bit, when at 1 (default), the blanking level (one of two according to PLL1 status) is made available on the HLckVBk permanently. The permanent blanking, irrespective of the BlankMode I²C-bus bit, is also provided if the supply voltage is low (under V_{CCEn} or V_{CCDis} thresholds), if the X-ray protection is active or if the V-drive signal is disabled by VOutEn I²C-bus bit.

Figure 18. Levels on HLckVBk composite output

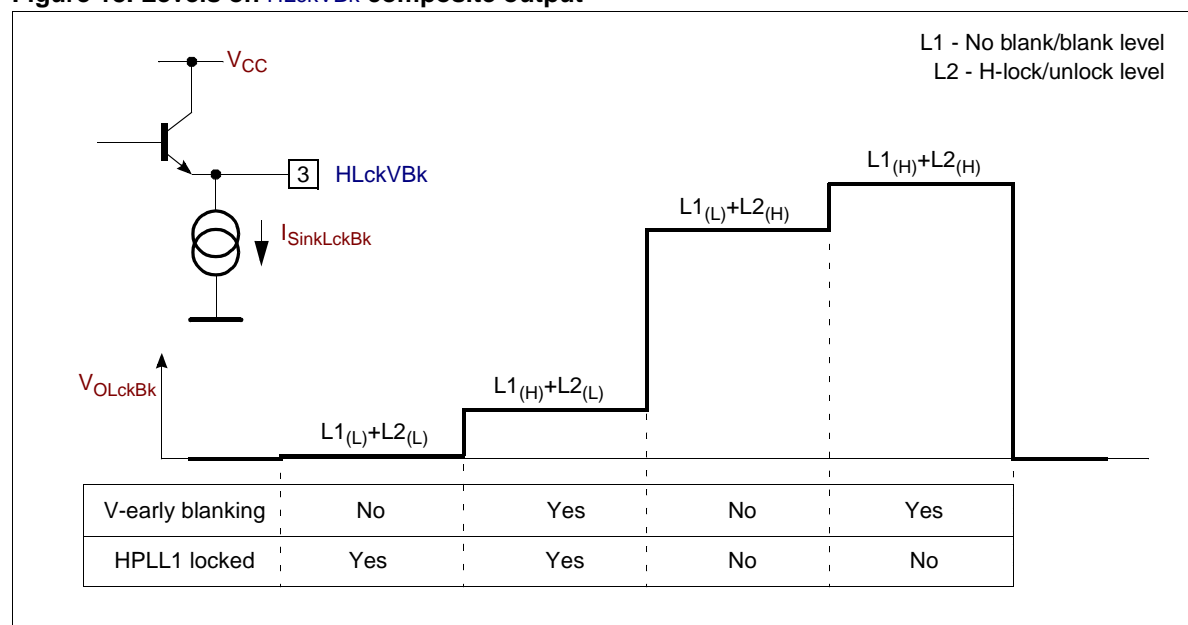
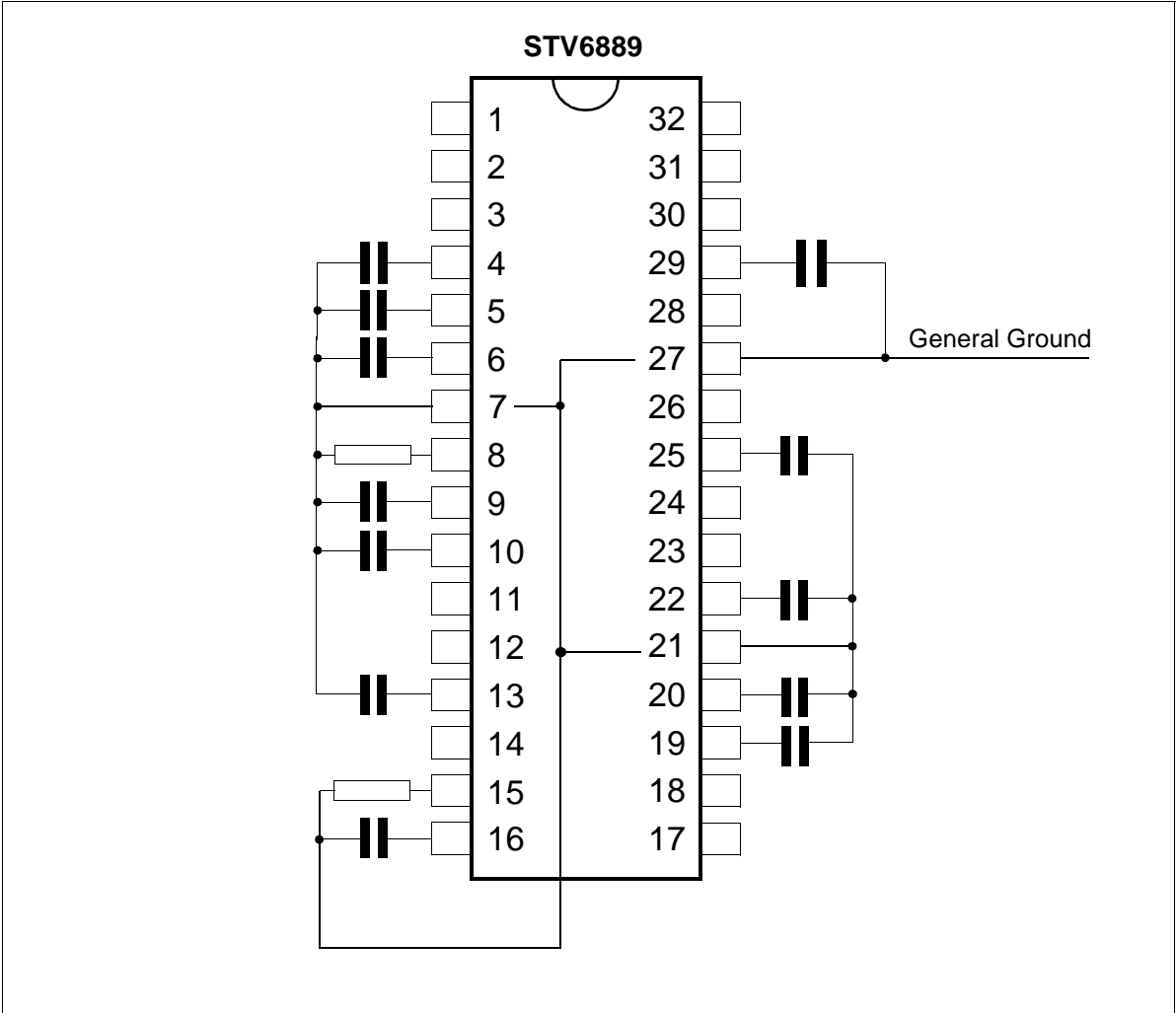


Figure 19. Ground layout recommendations



[illegible]

The diagram shows a 6-bit DAC circuit. On the left, a 6-bit digital input 'CO' (bits 0 to 5) is connected to a resistor ladder. The ladder consists of resistors connected to V_{CC} and ground. The output of the ladder is connected to a current mirror. The current mirror is composed of several transistors, including a reference transistor connected to V_{RefO} . The output of the current mirror is connected to a resistor ladder that produces the analog output voltage.

Figure 26.

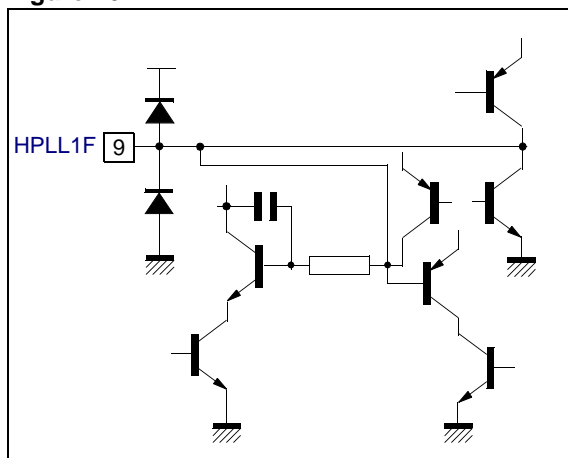


Figure 29.

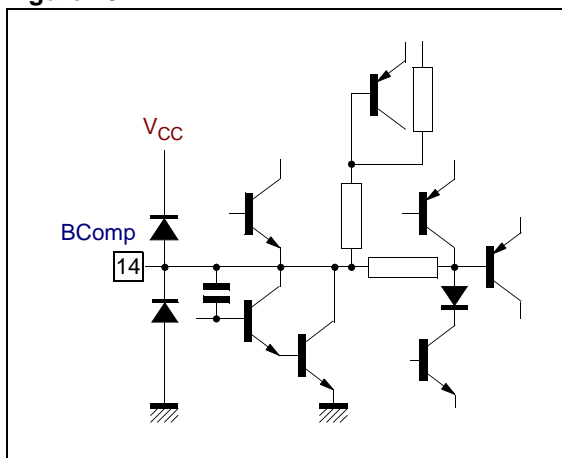


Figure 27.

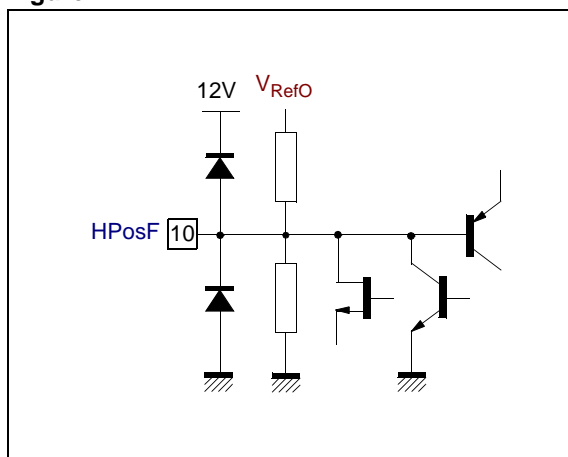


Figure 30.

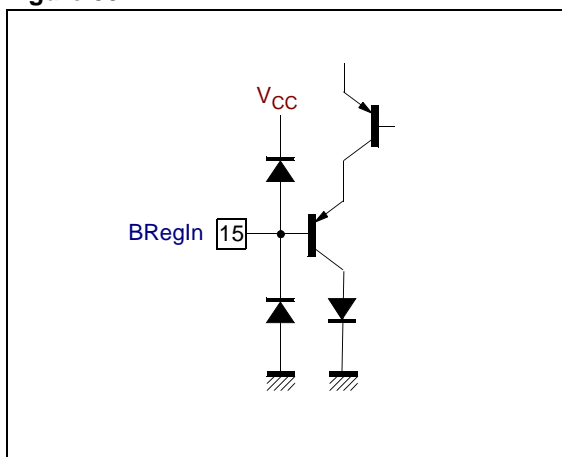


Figure 28.

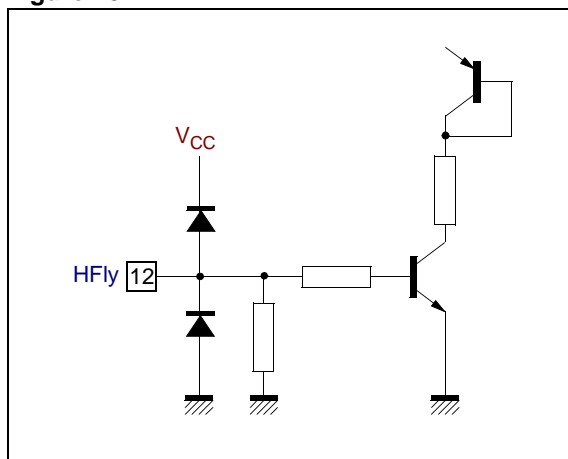


Figure 31.

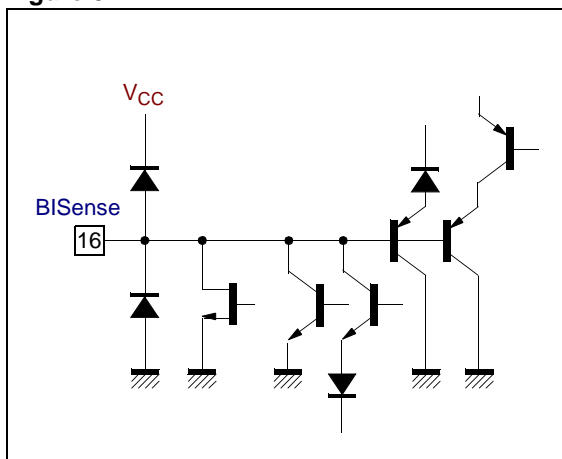


Figure 32.

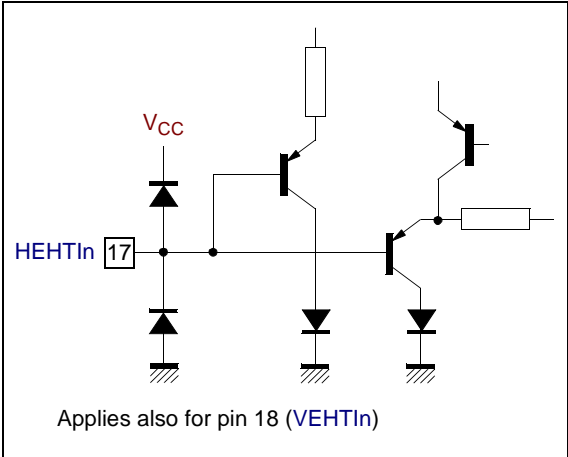


Figure 33.

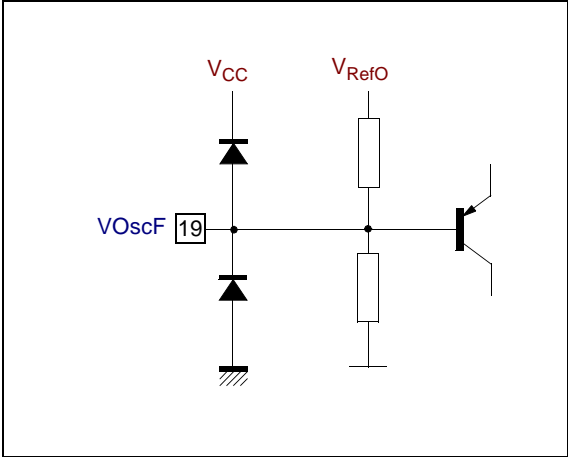


Figure 34.

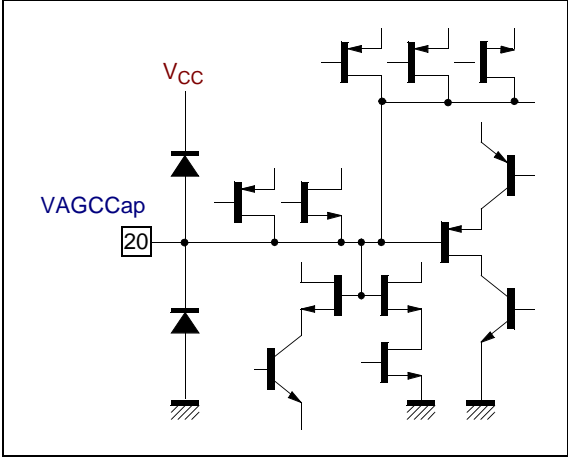


Figure 35.

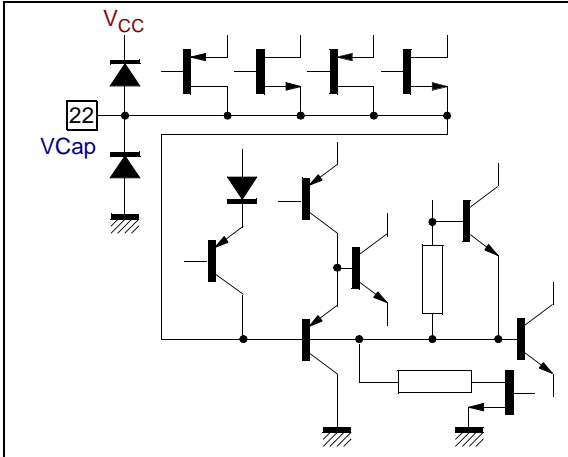


Figure 36.

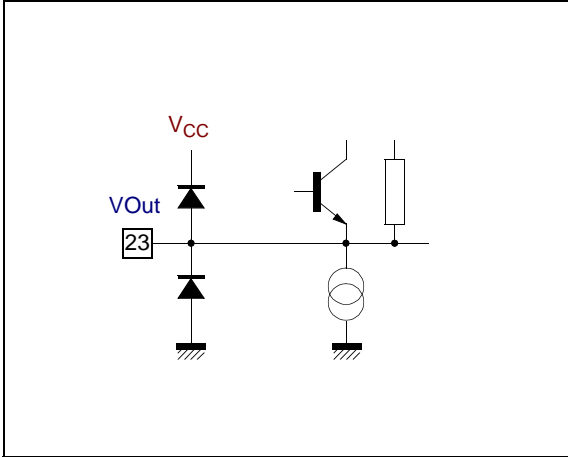


Figure 37.

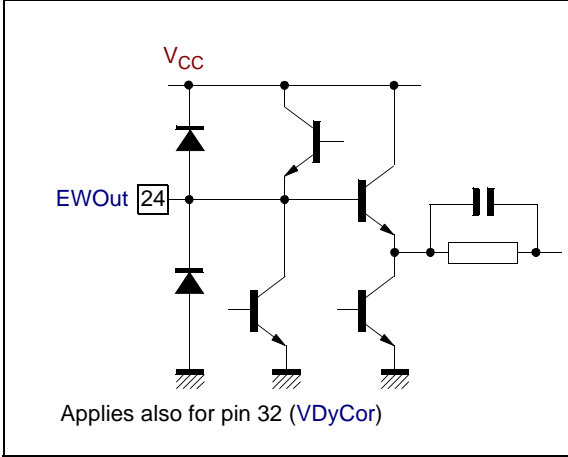


Figure 38.

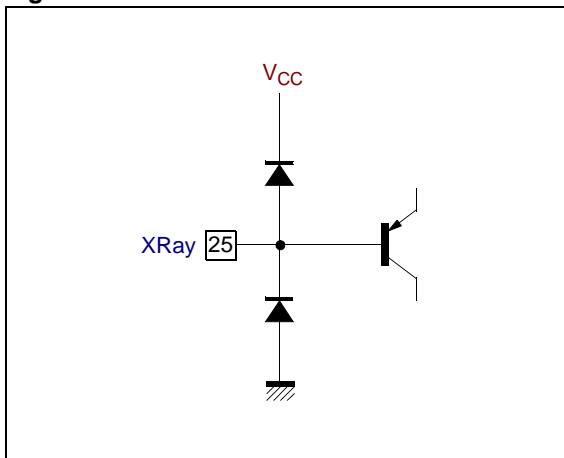


Figure 39.

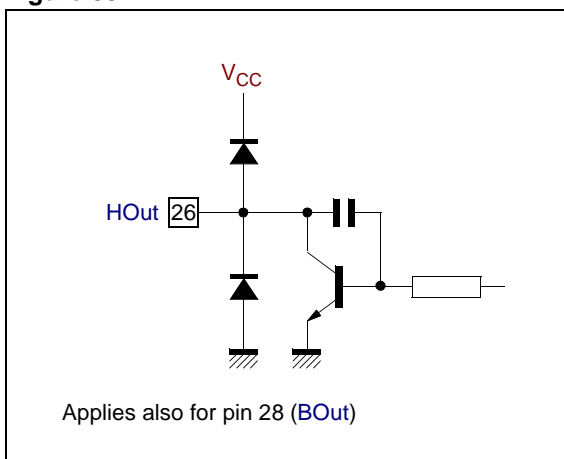
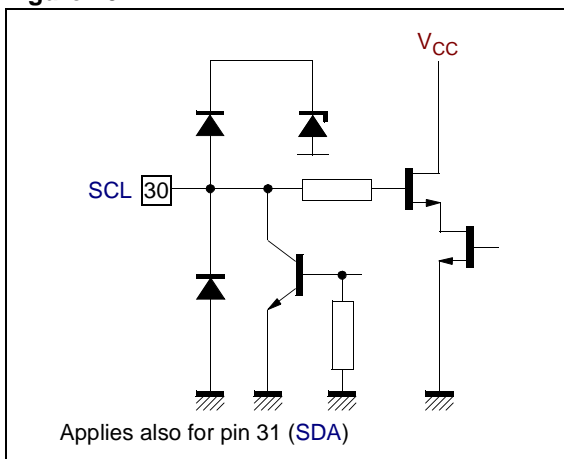
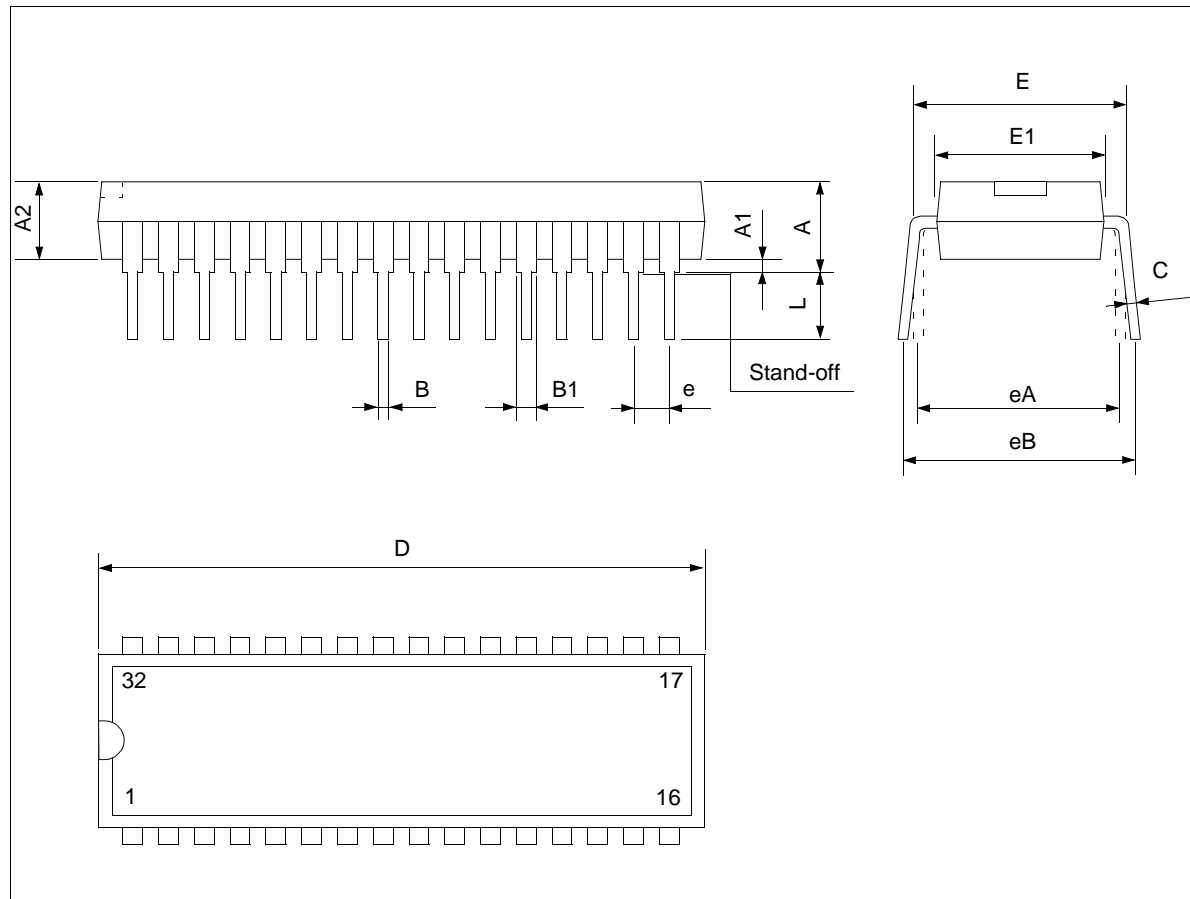


Figure 40.



11 PACKAGE MECHANICAL DATA

32 PINS - PLASTIC SHRINK



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	3.556	3.759	5.080	0.140	0.148	0.200
A1	0.508			0.020		
A2	3.048	3.556	4.572	0.120	0.140	0.180
B	0.356	0.457	0.584	0.014	0.018	0.023
B1	0.762	1.016	1.397	0.030	0.040	0.055
C	.203	0.254	0.356	0.008	0.010	0.014
D	27.43	27.94	28.45	1.080	1.100	1.120
E	9.906	10.41	11.05	0.390	0.410	0.435
E1	7.620	8.890	9.398	0.300	0.350	0.370
e		1.778			0.070	
eA		10.16			0.400	
eB			12.70			0.500
L	2.540	3.048	3.810	0.100	0.120	0.150

12 GLOSSARY

AC	A lternate C urrent
ACK	ACK nowledge bit of I ² C-bus transfer
AGC	A utomatic G ain C ontrol
COMP	COMP arator
CRT	C athode R ay T ube
DC	D irect C urrent
EHT	E xtra H igh V oltage
EW	E ast- W est
H/W	H ard W are
HOT	H orizontal O utput T ransistor
I²C	I nter- I ntegrated C ircuit
IIC	I nter- I ntegrated C ircuit
MCU	M icro- C ontroller U nit
NAND	N egated AND (logic operation)
NPN	N egative- P ositive- N egative
OSC	OSC illator
PLL	P hase- L ocked L oop
PNP	P ositive- N egative- P ositive
REF	REF erence
RS, R-S	R eset- S et
S/W	S oft W are
TTL	T ransistor T ransistor L ogic
VCO	V oltage- C ontrolled O scillator

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